

**P90X0 MVME224-1 / MVME224-2
4M / 8M byte Memory Modules**

Field Support Manual



PHILIPS



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4M / 8M byte Memory Modules**

Field Support Manual

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Great care has been taken to ensure that the information contained in this handbook is accurate and complete. Should any errors or omissions be discovered or should any user wish to make a suggestion for improving this handbook, he is invited to send the relevant details to:

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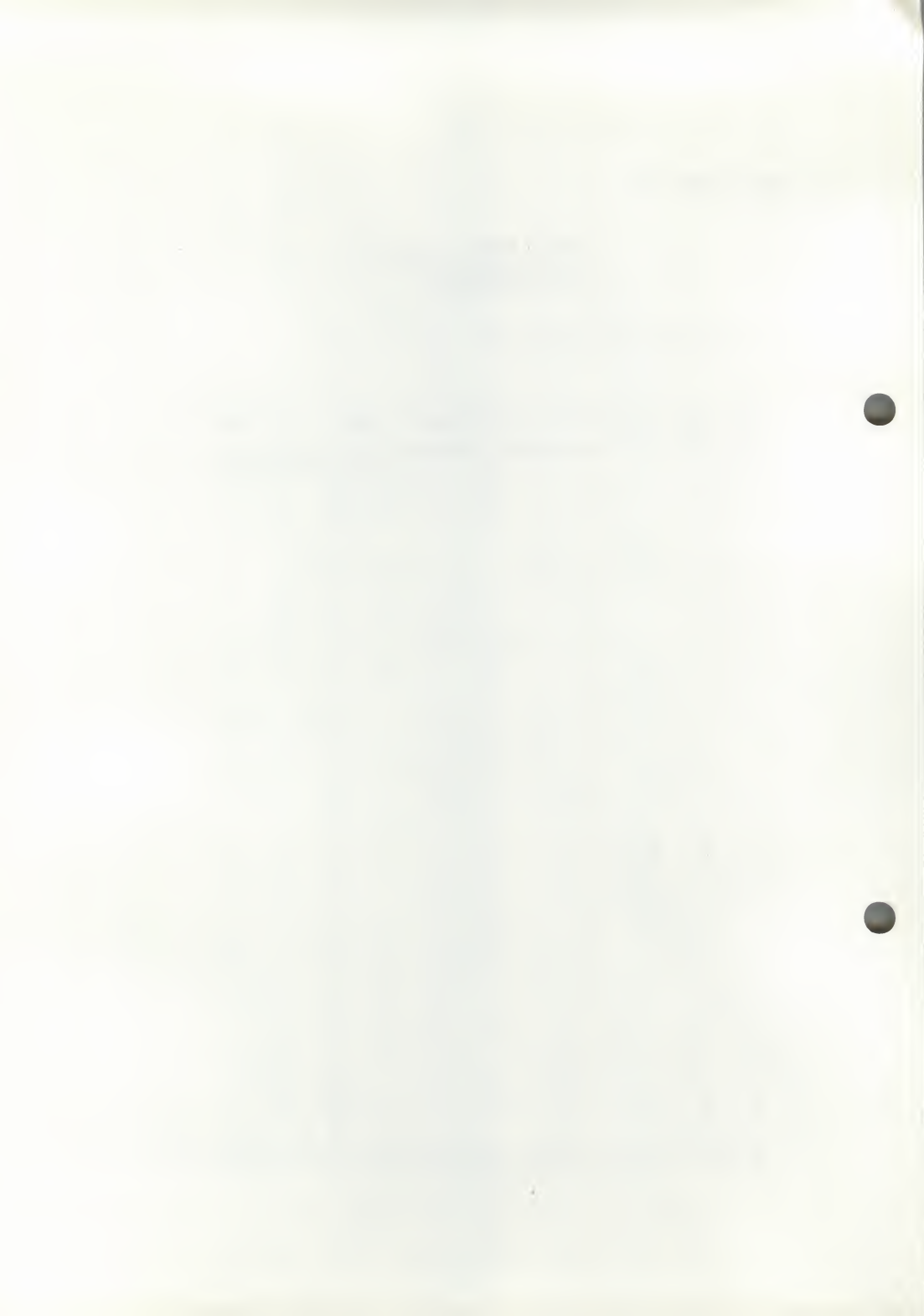
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Preface

This manual provides general information, hardware preparation, installation instructions, functional description, and support information for the MVME224 series of DRAM memory modules.

This manual is intended for anyone who wants to design OEM systems, supply additional capability to an existing compatible system or in a lab environment for experimental purposes.

A basic knowledge of computers and digital logic is assumed.

To use this manual, you should be familiar with the publications listed in the *Related Documentation* paragraph in Chapter 1 of this manual.

The information in this document about the MVME224 module jumper setting is not explicit for the P90X0 configuration.

To be sure having the correct jumper setting, refer to the Customer Engineer Manual P90X0 or to the Installation Instructions delivered with the MVME224 board.

The part numbers in the section 4.3 are the Motorola part numbers. These numbers can be incorrect.

For the correct numbers see the Spare Parts P90X0 manual distributed by Customer Service Logistics.

A copy of the current MVME224-2 part of this manual is included at the rear of this manual. There is no list available for the MVME224-1 because this board is not released within the P90X0 family.

WARNING

THIS EQUIPMENT GENERATES, USES, AND CAN RADIATE RADIO FREQUENCY ENERGY AND IF NOT INSTALLED AND USED IN ACCORDANCE WITH THE INSTRUCTIONS MANUAL, MAY CAUSE INTERFERENCE TO RADIO COMMUNICATIONS. IT HAS BEEN TESTED AND FOUND TO COMPLY WITH THE LIMITS FOR A CLASS A COMPUTING DEVICE PURSUANT TO SUBPART J OF PART 15 OF FCC RULES, WHICH ARE DESIGNED TO PROVIDE REASONABLE PROTECTION AGAINST SUCH INTERFERENCE WHEN OPERATED IN A COMMERCIAL ENVIRONMENT. OPERATION OF THIS EQUIPMENT IN A RESIDENTIAL AREA IS LIKELY TO CAUSE INTERFERENCE IN WHICH CASE THE USER, AT HIS OWN EXPENSE, WILL BE REQUIRED TO TAKE WHATEVER MEASURES NECESSARY TO CORRECT THE INTERFERENCE.

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First Edition

SAFETY SUMMARY

SAFETY DEPENDS ON YOU

The following general safety precautions must be observed during all phases of operation, service, and repair of this equipment. Failure to comply with these precautions or with specific warnings elsewhere in this manual violates safety standards of design, manufacture, and intended use of the equipment. Motorola Inc. assumes no liability for the customer's failure to comply with these requirements. The safety precautions listed below represent warnings of certain dangers of which we are aware. You, as the user of the product, should follow these warnings and all other safety precautions necessary for the safe operation of the equipment in your operating environment.

GROUND THE INSTRUMENT.

To minimize shock hazard, the equipment chassis and enclosure must be connected to an electrical ground. The equipment is supplied with a three-conductor ac power cable. The power cable must either be plugged into an approved three-contact electrical outlet or used with a three-contact to two-contact adapter, with the grounding wire (green) firmly connected to an electrical ground (safety ground) at the power outlet. The power jack and mating plug of the power cable meet International Electrotechnical Commission (IEC) safety standards.

DO NOT OPERATE IN AN EXPLOSIVE ATMOSPHERE.

Do not operate the equipment in the presence of flammable gases or fumes. Operation of any electrical equipment in such an environment constitutes a definite safety hazard.

KEEP AWAY FROM LIVE CIRCUITS.

Operating personnel must not remove equipment covers. Only Factory Authorized Service Personnel or other qualified maintenance personnel may remove equipment covers for internal subassembly or component replacement or any internal adjustment. Do not replace components with power cable connected. Under certain conditions, dangerous voltages may exist even with the power cable removed. To avoid injuries, always disconnect power and discharge circuits before touching them.

DO NOT SERVICE OR ADJUST ALONE.

Do not attempt internal service or adjustment unless another person, capable of rendering first aid and resuscitation, is present.

USE CAUTION WHEN EXPOSING OR HANDLING THE CRT.

Breakage of the Cathode-Ray Tube (CRT) causes a high-velocity scattering of glass fragments (implosion). To prevent CRT implosion, avoid rough handling or jarring of the equipment. Handling of the CRT should be done only by qualified maintenance personnel using approved safety mask and gloves.

DO NOT SUBSTITUTE PARTS OR MODIFY EQUIPMENT.

Because of the danger of introducing additional hazards, do not install substitute parts or perform any unauthorized modification of the equipment. Contact Motorola Field Service Division for service and repair to ensure that safety features are maintained.

DANGEROUS PROCEDURE WARNINGS.

Warnings, such as the example below, precede potentially dangerous procedures throughout this manual. Instructions contained in the warnings must be followed. You should also employ all other safety precautions which you deem necessary for the operation of the equipment in your operating environment.

WARNING

Dangerous voltages, capable of causing death, are present in this equipment. Use extreme caution when handling, testing, and adjusting.

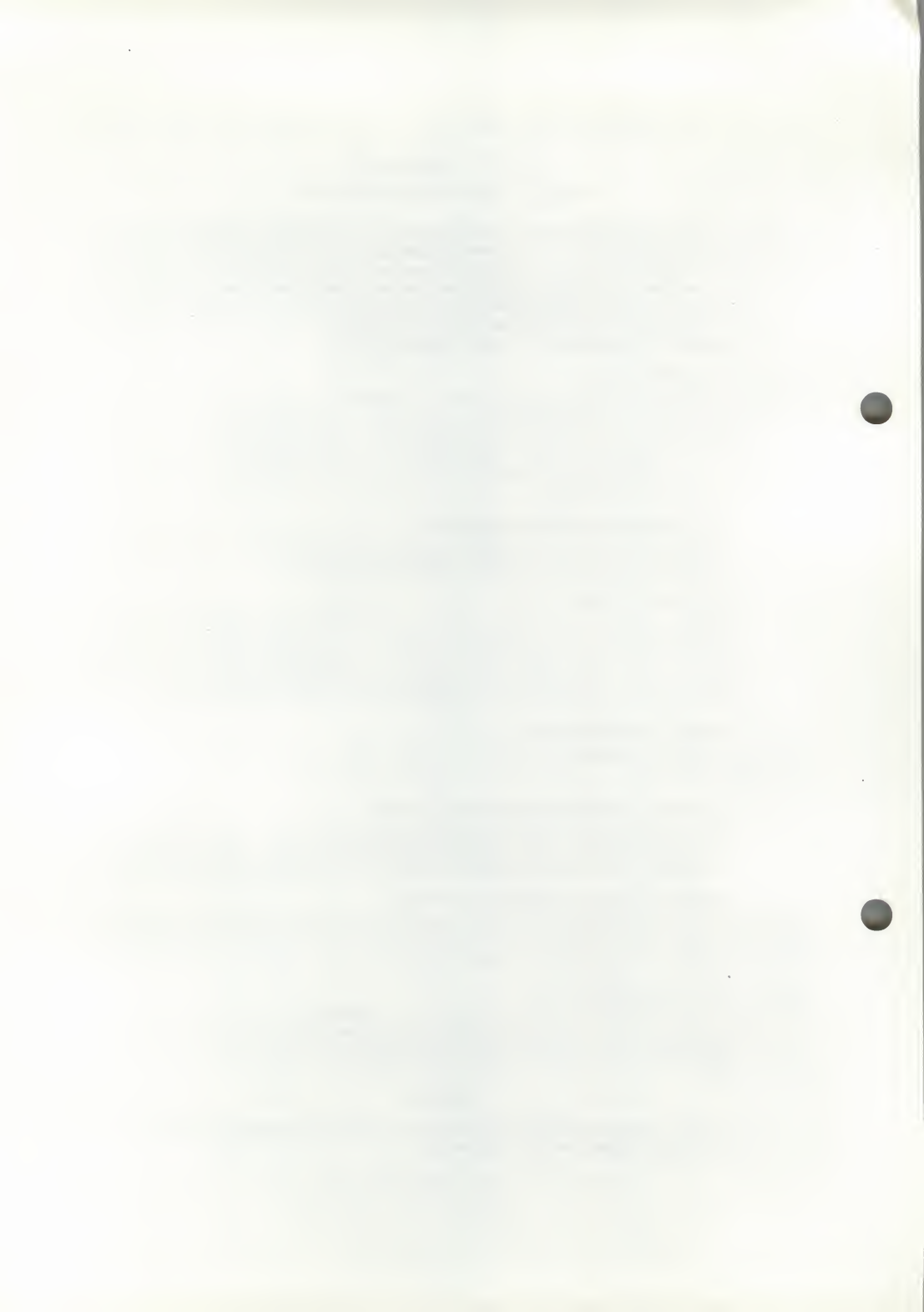


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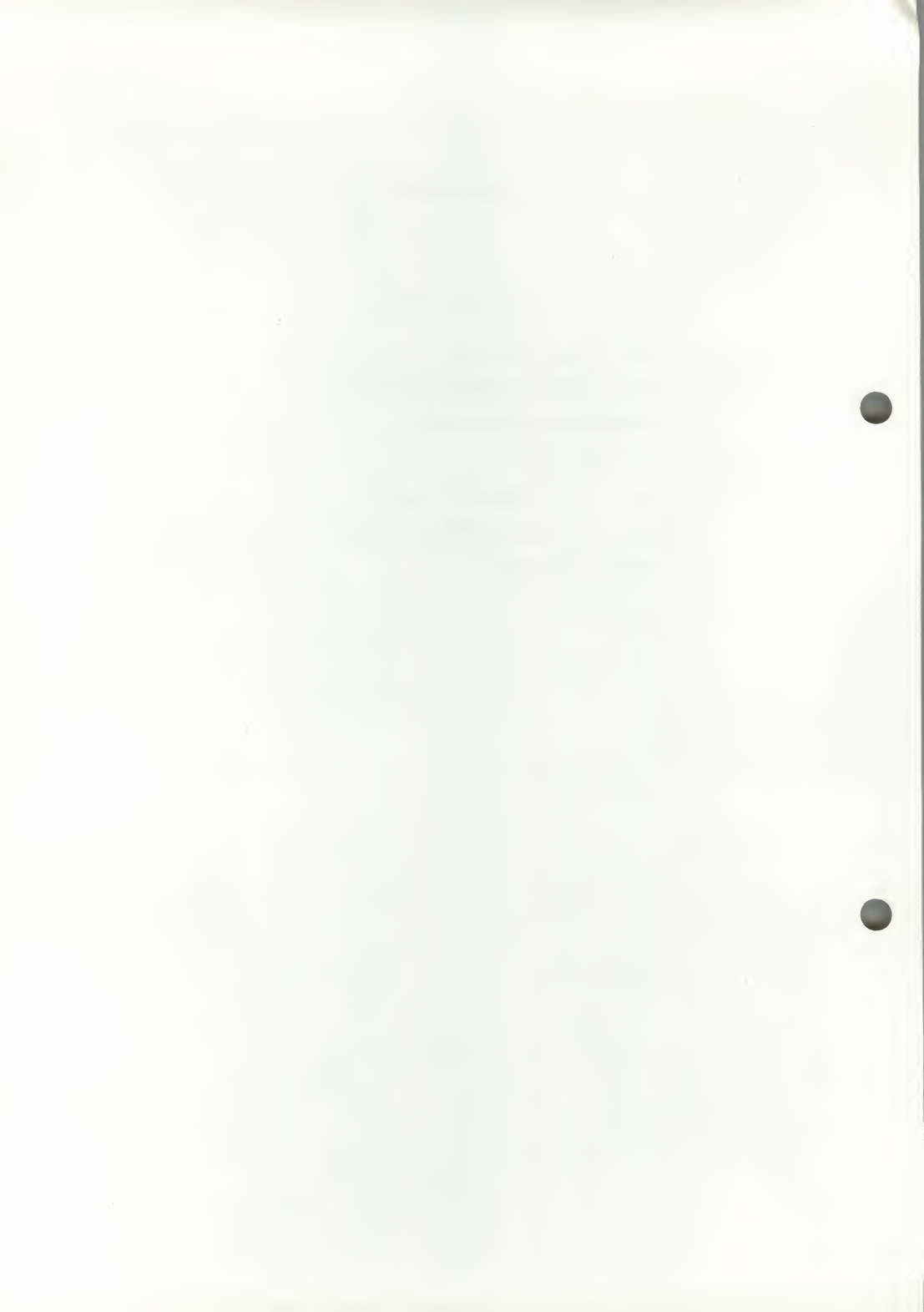
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CHAPTER 1 - GENERAL INFORMATION

1.1 INTRODUCTION

This user's manual provides general information, preparation and installation instructions, functional description, and support information for the MVME224-1 (4 Megabyte) and MVME224-2 (8 Megabyte) DRAM Memory Modules with VME/VSB Interface. These modules are referred to as the MVME224 throughout the remainder of this manual.

1.2 FEATURES

The features of the MVME224 include:

- Memory Capacity - 4Mb or 8Mb using 1-megabit DRAMs in ZIP packages.
- Dual ported VMEbus interface with 16-/24-/32-bit address selection and 16-/32-bit data.
- Multiplexed VSB interface with 32-bit address/data.
- Longword (32-bit), Word (16-bit), and byte (8-bit) data transfers.
- Memory base address switch-selectable on any 1Mb boundary throughout the VMEbus and VSB address space.
- Error Protection -- Parity is provided on a byte basis.
- Command and Status Register -- Control over parity and error status reporting.
- Fast Read -- Selectable to start reads on PAS* on VSB for fast access or DS* to allow a cache detection.
- Fast Write -- Both VMEbus and VSB provide early DTACK on a write access.

1.3 SPECIFICATIONS

General specifications for the MVME224 are provided in Table 1-1.

TABLE 1-1. MVME224 SPECIFICATIONS

Characteristic	Specification
Storage capacity:	
MVME224-1	4 Megabytes
MVME224-2	8 Megabytes
Data transfer size	8-, 16-, and 32-bit

GENERAL INFORMATION

TABLE 1-1. MVME224 SPECIFICATIONS (cont.)

Characteristic	Specification
Error detection	Odd byte parity
Data Input/Output	16-32-bit VMEbus, 32-bit VSB
Input address	16-/24-/32-bit VMEbus, 32-bit VSB
Power requirements:	
MVME224-1	+4.75 to 5.25 Vdc at 5 A maximum (3.9A typical)
MVME224-2	+4.75 to 5.25 Vdc at 5 A maximum (3.9A typical)
Relative humidity	5% to 95% (non-condensing)
Temperature:	
Operating	0 degree to 50 degrees C inlet air temperature with forced air cooling.
Storage	-40 degrees to 85 degrees C
Physical size (PCB):	
Height x width	6.30 inches (16.00 cm) x 9.19 inches (23.34 cm)
Thickness	0.062 inch (0.157 cm)
Part projections:	
Component side	0.50 inch (1.27 cm) maximum
Solder side	0.067 inch (0.17 cm) maximum

1.4 GENERAL DESCRIPTION

The MVME224 module is a high performance dynamic memory module, dual ported to both the VMEbus and VSB bus. Both modules can be mapped to start on any 1Mb boundary and extend by the module (board) size. The MVME224 uses an advanced arbitration method which buries the arbitration time for the next cycle in the current cycle, thus increasing throughput.

1.5 REFERENCE DOCUMENTATION

The following publications provide additional helpful information. If not shipped with this product, they may be purchased from the Motorola Literature Distribution Center, 616 West 24th Street, Tempe Arizona 85282; telephone (602) 994-6561.

DOCUMENT TITLE	MOTOROLA PUBLICATION NUMBER
VMEbus Specification (Rev C.1)	HB212/D
VME Subsystem Bus (VSB) Specification	MVMESB

1.6 MANUAL TERMINOLOGY

Throughout this manual, a convention has been maintained whereby data and address parameters are preceded by a character which specifies the numeric format as follows:

\$	dollar	specifies a hexadecimal number
%	percent	specifies a binary number
&	ampersand	specifies a decimal number

Unless otherwise specified, all address references are in hexadecimal throughout this manual.

An asterisk (*) following the signal name for signals which are level significant denotes that the signal is true or valid when the signal is low.

An asterisk (*) following the signal name for signals which are edge significant denotes that the actions initiated by that signal occur on high to low transition.

In this manual, assertion and negation are used to specify forcing a signal to a particular state. In particular, assertion and assert refer to a signal that is active or true; negation and negate indicate a signal that is inactive or false. These terms are used independently of the voltage level (high or low) that they represent.

GENERAL INFORMATION

CHAPTER 2 - HARDWARE PREPARATION AND INSTALLATION**2.1 INTRODUCTION**

This chapter provides the unpacking, hardware preparation, and installation instructions for the MVME224 memory modules. It also describes the start-up procedures.

2.2 UNPACKING INSTRUCTIONS**NOTE**

If shipping carton is damaged upon receipt, request that the carrier's agent be present during unpacking/inspection of equipment.

Carefully unpack the equipment from the shipping carton. Refer to the packing list and verify that all items are present. Save the shipping carton and packing materials for storing or reshipping of the equipment.

CAUTION

AVOID TOUCHING AREAS OF INTEGRATED CIRCUITS;
STATIC DISCHARGE CAN DAMAGE THESE CIRCUITS.

Inspect for any shipping damage. If no damage exists, then the module can be prepared for operation according to the following sections of this chapter.

2.3 HARDWARE PREPARATION

This section describes the hardware preparation of the MVME224 memory module prior to installation. Observance of this description will ensure the user that all components are properly configured for operation.

Jumper blocks are used to select the various functions and options of the MVME224 memory module. Before the MVME224 is installed, the user should verify the jumper block configurations and alter the jumpers, as required, for the user's particular system operation.

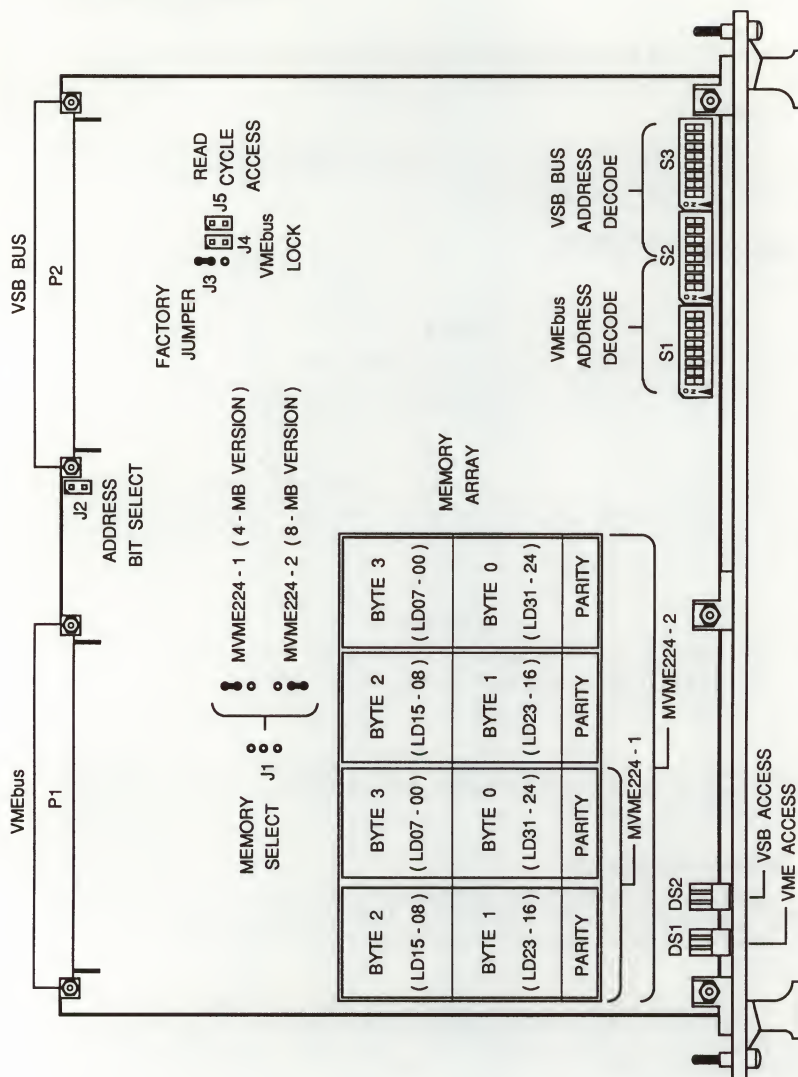


FIGURE 2-1. MVME224 JUMPER, CONNECTOR, AND SWITCH LOCATION DIAGRAM

The MVME224 has been factory tested and is shipped with factory-installed jumper configurations that are illustrated in Figure 2-1. The MVME224 is operational with these factory-installed jumpers. Table 2-1 lists the jumper blocks by designation, function, and factory configuration. A more detailed description of these jumper blocks is provided in the following sections.

Also, three DIP-type switches (S1, S2, and S3) are located on the MVME224. For detailed information regarding the use of these three switches, refer to section 2.3.7.

2.3.1 Jumper Block Settings

The following table lists and describes the MVME224 jumper blocks.

TABLE 2-1. MVME224 FACTORY JUMPER PLACEMENTS

Jumper	Function	Factory Configuration
J1	Memory Selection (Soldered Staple Jumper)	J1(1-2) (MVME224-1, 4Mb version) J1(2-3) (MVME224-2, 8Mb version)
J2	Address Bit Selection	No Jumper(s) Installed.
J3	Factory Jumper (Soldered Staple Jumper)	J3(1-2) (All versions)
J4	VMEbus Lock	No Jumper(s) Installed.
J5	Read Cycle Access	No Jumper(s) Installed.

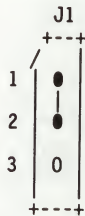
HARDWARE PREPARATION

2.3.2 Memory Selection (J1)

Jumper block J1 determines the memory selection of the MVME224 memory module. A staple pin is factory soldered across jumper J1 pins 1-2 on the MVME224-1 (4Mb version) and across jumper J1 pins 2-3 on the MVME224-2 (8Mb version).

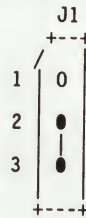
Jumper Block J1
Memory Selection
4-Megabyte Version
(Factory Setting)

=====



Jumper Block J1
Memory Selection
8-Megabyte Version
(Factory Setting)

=====

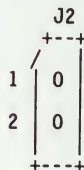


2.3.3 Address Bit Selection (J2)

Jumper block J2 determines the address bit selection. With no jumper installed, 24- or 32-bit addressing is allowed. With a jumper installed across jumper J2 pins 1-2, 24-bit address modifiers will not be decoded and the module will not respond to 24-bit addresses.

Jumper Block J2
Address Bit Selection
No Jumper Installed
(Factory Setting)

=====



2.3.4 Factory Jumper (J3)

Jumper block J3 is for factory use only. A staple pin is factory soldered across J3 pins 1 and 2 in all versions of the MVME224 Revision B memory modules. This jumper block does not exist on MVME224 Revision C memory modules.

Jumper Block J3
Factory Jumper Only
(Factory Setting)

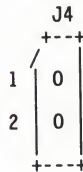
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**2.3.5 VMEbus Lock (J4)**

In systems that support the VMELOCK signal option (such as the MVME130, MVME131, MVME135, or MVME141), installing a jumper pin across J4 pins 1 and 2 will allow control of locking the VMEbus. Normally, the VSB bus is locked out until Address Strobe (AS*) on the VMEbus returns to high, as there is no way to detect a read-modify-write cycle. If this jumper is installed, only those cycles that allow VMELOCK* to go high are locked and the MVME224 is allowed to start a VSB bus cycle sooner; not waiting for the VMEbus AS* to return high. The VMELOCK signal is driven by the bus master on the reserved bus pin P2-B3.

Jumper Block J4
VMEbus Lock
No Jumper Installed
(Factory Setting)

=====



HARDWARE PREPARATION

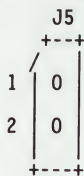
2.3.6 Read Cycle Access (J5)

Jumper block J5 serves two functions. First, it determines whether a read cycle will start from PAS* or DS* on the VSB bus. In some systems doing caching, the master will drive addresses and PAS* during the time it is decoding a potential local cache hit. If a cache hit is found, it simply removes the strobes without driving DS* or completing the cycle. Installing a mini-jumper across pins 1 and 2, starts read cycles on DS* to avoid starting false cycles. Systems not employing these address-only cache cycles should start reads on PAS* (i.e., with the jumper not installed).

Secondly, jumper block J5 also determines whether the WAIT* signal will be driven. In a system with one or more slaves who decode and drive ASACK0* or ASACK1* in less than 50 nanoseconds, jumper J5 should be installed. Installing jumper J5 causes the MVME224 to drive the WAIT* signal and forces the master to hold addresses stable until decoding is done by the MVME224. This slows system performance slightly, so it should be avoided unless necessary. In a system where all slaves are MVME224s, or no slaves are capable of decoding addresses and driving ASACK0* or ASACK1* in less than 50 nanoseconds from PAS*, do not install jumper J5.

Jumper Block J5
Read Cycle Access
No Jumper Installed -
(Factory Setting)

=====



2.3.7 VME/VSB Address Decode Switches

DIP switches S1, S2, and S3 are used in selecting the starting address for the VMEbus and the VSB bus mapping. Addressing is independently selectable on 1Mb boundaries.

The VME portion of the switches is also used in selecting the starting address for the CSR mapping. The CSR is mapped dependent on the mapping of the addressing to the RAMs on the VMEbus. The following examples illustrate how the switch positions can be set for any required address.

HARDWARE PREPARATION

Example: VMEbus Address Mapping (S1-1 to S1-8 and S2-1 to S2-4) on 1Mb boundaries.

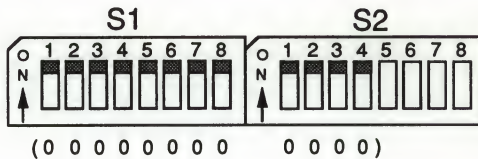
CSR Mapping - Base address is BE01, increasing 4 bytes for each 2Mb increase of RAM base address.

BEGINNING ADDRESS

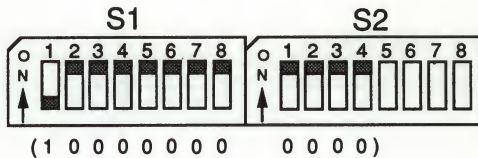
SWITCH S1

SWITCH S2

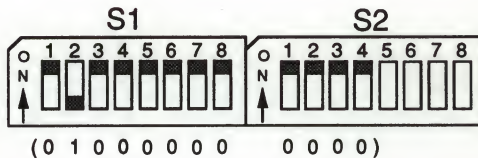
0 0 0 0 0 0 0 0 =
(CSR ADDR: BE01)



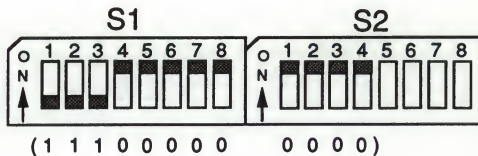
0 0 1 0 0 0 0 0 =
(CSR ADDR: BE01)



0 0 2 0 0 0 0 0 =
(CSR ADDR: BE05)



0 0 7 0 0 0 0 0 =
(CSR ADDR: BE0C)



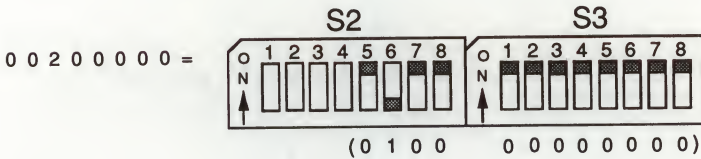
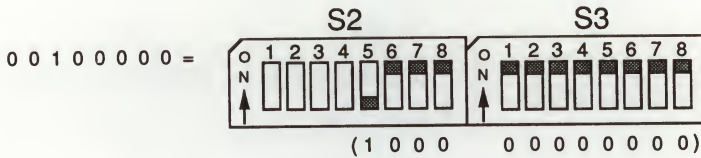
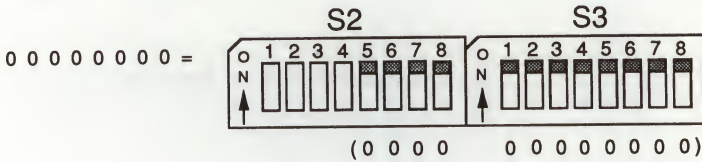
HARDWARE PREPARATION

Example: VSB Bus Address Mapping (S2-5 to S2-8 and S3-1 to S3-8) on 1Mb boundaries.

BEGINNING ADDRESS

SWITCH S2

SWITCH S3



2.4 INSTALLATION INSTRUCTIONS

After the MVME224 has been properly configured for operation, it is ready for installation in a VME module chassis.

1. Ensure that power is turned **OFF** to the chassis and that the board ejector handles are in their non-eject positions.

CAUTION

INSERTING OR REMOVING THE BOARD WHILE POWER IS APPLIED CAN DAMAGE THE BOARD CIRCUITRY. AVOID TOUCHING AREAS OF INTEGRATED CIRCUITS; STATIC DISCHARGE CAN DAMAGE THESE CIRCUITS.

2. The Bus Grant and IACK backplane jumpers may either be installed or removed in the card slot in which the MVME224 is installed. The MVME224 does not use these signals.
3. Slide the board into the board slides of the selected slot until the P1/P2 connectors align and seat into their backplane sockets. Press firmly on the top and bottom sections of the front panel until the connectors seat fully into their backplane sockets. Avoid pressing against the board ejector handles as they may slide into their board eject positions. When installing, check the position of the two captive screws at the top and bottom ends of the front panel. They may jam against the chassis frame and prevent the board from seating fully.
4. Once installed, screw in the two captive screws to secure the board in place. Avoid over-tightening the screws as they may strip out the screw sockets. The screws also serve to electrically connect the front panel to the frame of the chassis by pressing the conductive top and bottom sections of the front panel against the conductive frame of the chassis. This integrates the front panel into the EMI (Electromagnetic Interference) shield of the chassis. This also reduces the susceptibility of the board to static discharge that can result from touching the front panel. These EMI protections rely on the use of a chassis that is properly designed to control the susceptibility and emission of EMI.
5. Connect the power cable to the AC power source and turn the unit **ON**.

HARDWARE PREPARATION

CHAPTER 3 - FUNCTIONAL DESCRIPTION**3.1 INTRODUCTION**

This chapter provides an overall block diagram view of the MVME224 memory module. The discussion includes sections with detailed descriptions of the 4/8Mb DRAM array, the DRAM timing and control circuitry with dual port and refresh arbitration, the VMEbus interface and address decode, the VSB bus interface and address decode, parity generation and checking, and the Control/Status Register. For the purpose of the following description, the MVME224 is regarded as consisting of functional blocks as illustrated in Figure 3-1. For further details, refer to the schematic diagram in Chapter 4 and to the VMEbus Specification Manual (Motorola publication HB212/D).

3.2 DRAM ARRAY

The MVME224-1 (4Mb version) provides a DRAM array of 36 1-megabit DRAMs in zip packages. The MVME224-2 (8Mb version) provides a DRAM array of 72 1-megabit DRAMs in zip packages. The DRAM array is arranged in 4 bytes with 1 parity bit per byte on the 4Mb version, or 8 bytes with 1 parity bit per byte on the 8Mb version.

CAS before RAS refresh is utilized, using the address counter internal to the DRAMs, therefore, no refresh addresses must be supplied.

3.3 DRAM TIMING, CONTROL, AND ARBITRATION

DRAM timing, arbitration of the internal bus between VMEbus and VSB bus, and refresh arbitration are all accomplished from two timing chains. The $T0^*$ timing handles arbitration while the $RAST0^*$ timing handles RAM signals. One of the potential users of the arbitration scheme (VMEbus, VSB bus, and refresh) will have control at any time. When a request for a cycle is generated from either of the address decode circuits or the refresh circuit, the $T0^*$ timing chain is started. This timing chain will cause arbitration to take place. If the user that generated the request is the same as the one which has the internal control, then the $RAST0^*$ timing is also started. This will cause a memory cycle, or CSR cycle to take place. The third possibility is that a cycle can be started on the $T0^*$ timing chain by a user not having control causing an arbitration cycle to start. If within 50 nanoseconds, a cycle is decoded on the circuit which does have control, the $RAST0^*$ timing chain will start causing what started as an arbitration only cycle to become also a valid memory cycle.

FUNCTIONAL DESCRIPTION

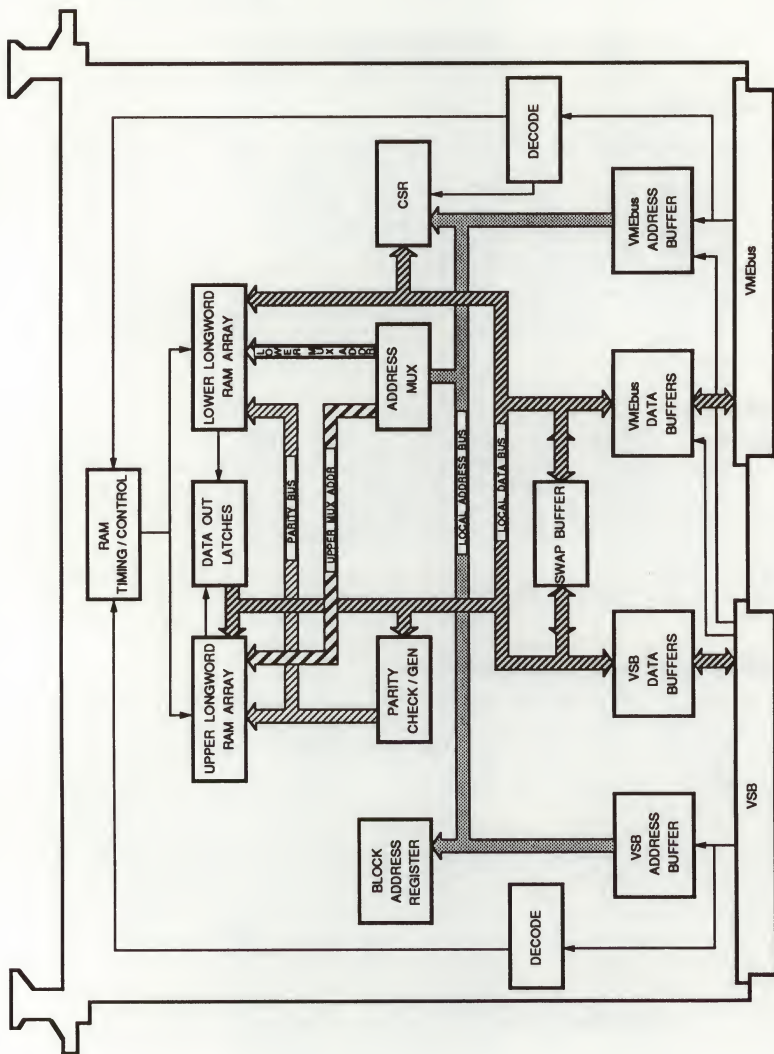


FIGURE 3-1. MVME224 BLOCK DIAGRAM

FUNCTIONAL DESCRIPTION

In each case, an arbitration is done midway in the cycle to determine who will have control for the next cycle. In the case of a refresh cycle, it is always arbitrated back to either VME or VSB. It will go to VSB if a VSB cycle is pending, to VME if a VME cycle is pending with no VSB pending, or, if neither has a cycle pending, back to the one that preceded it. The result of this arbitration method is greater performance and, under heavy loading of both busses, performance actually increases over light loading of both busses.

The read cycle timing diagram is illustrated in Figure 3-2. The write cycle timing diagram is illustrated in Figure 3-3.

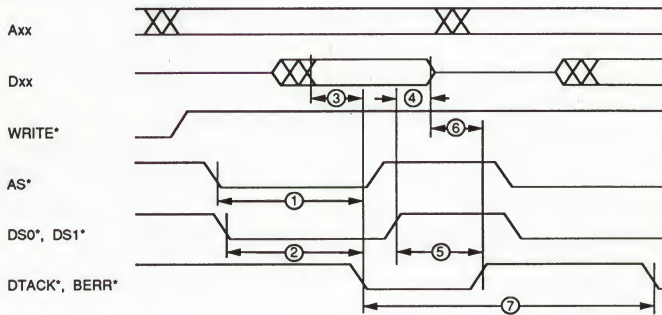


FIGURE 3-2. VME READ CYCLE TIMING

No.	Parameter	Min	Typ	Max	Unit	Notes
1	AS* low to DTACK*/BERR* low	185	190	485	nsec	1,3
2	DS0*/DS1* low to DTACK*/BERR* low	185	190	485	nsec	3
3	Data valid to DTACK* low	0	--	30	nsec	--
4	DS0*/DS1* high to data invalid	10	--	40	nsec	--
5	DS0*/DS1* high to DTACK*/BERR* high	15	20	30	nsec	--
6	Data high imp. to DTACK*/BERR* high	0	--	35	nsec	--
7	DTACK* low to DTACK* low	230	245	565	nsec	2,3

Notes:

- 1) Provided that the VMEbus master drives AS* and DS0*/DS1* low at the same time.
- 2) Provided that the VMEbus master drives DS0*/DS1* low less than 40 nsec after receiving DTACK* low.
- 3) The maximum time can result if a refresh cycle has just started when the board is selected, and a VSB cycle comes before the refresh cycle is finished.

FUNCTIONAL DESCRIPTION

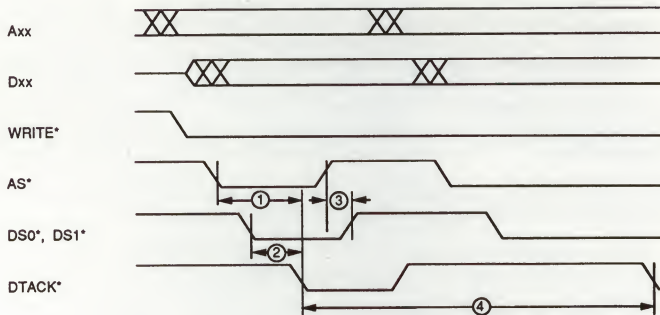


FIGURE 3-3. VME WRITE CYCLE TIMING

No.	Parameter	Min	Typ	Max	Unit	Notes
1	AS* low to DTACK* low	60	70	355	nsec	1,3
2	DS0*/DS1* low to DTACK* low	60	70	355	nsec	3
3	DS0*/DS1* high to data high	15	20	30	nsec	--
4	DTACK* low to DTACK* low	215	230	435	nsec	2,3

Notes:

- 1) Provided that the VMEbus master drives AS* and DS0*/DS1* low at the same time.
- 2) Provided that the VMEbus master drives DS0*/DS1* low less than 40 nsec after receiving DTACK* low.
- 3) The maximum time can result if a refresh cycle has just started when the board is selected, and a VSB cycle comes before the refresh cycle is finished.

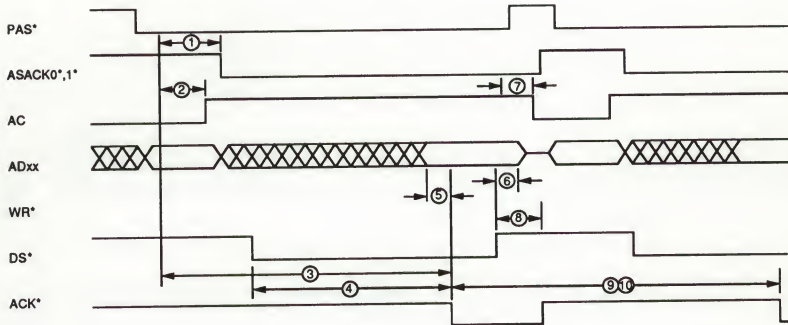


FIGURE 3-4. VSB READ CYCLE TIMING

No.	Parameter	Min	Typ	Max	Unit	Notes
1	PAS* low to ASACK0*/ASACK1* low	50	55	60	nsec	--
2	PAS* low to AC high	25	35	45	nsec	--
3	PAS* low to ACK* low	180	190	200	nsec	1,2
4	DS* low to ACK* low	180	190	200	nsec	2,3
5	Data valid on bus to ACK* low	10	15	--	nsec	--
6	PAS* high to data three-state on bus	10	15	20	nsec	--
7	PAS* high to AC low	10	15	20	nsec	--
8	PAS* high to ASACK0*/ASACK1* high	15	20	25	nsec	--
9	ACK* low to ACK* low	--	250	470	nsec	2,4,5
10	ACK* low to ACK* low	--	350	570	nsec	2,4,6

Notes:

- 1) With the cache mode jumper J5 not installed, read cycles begin on PAS*. ACK will be stated time or 20 nsec after DS* low if PAS* low to DS* low exceeds 170 nsec.
- 2) The maximum time can result if a refresh has just started when the board is selected.
- 3) With the cache mode jumper J5 installed, read cycles begin on DS*. Time stated in item 4 above applies.
- 4) Cycle time is dependent on handshakes and speed of master changing from address to data phases. These figures represent DS* low, 75 nsec after PAS* goes low, with ACK* low to DS* high = 10 nsec, DS* high to ACK* high = 15 nsec, and ACK* high to PAS* low = 30 nsec.
- 5) These figures are in non-cache mode, with jumper J5 not installed.
- 6) These figures are in cache mode, with jumper J5 installed.

FUNCTIONAL DESCRIPTION

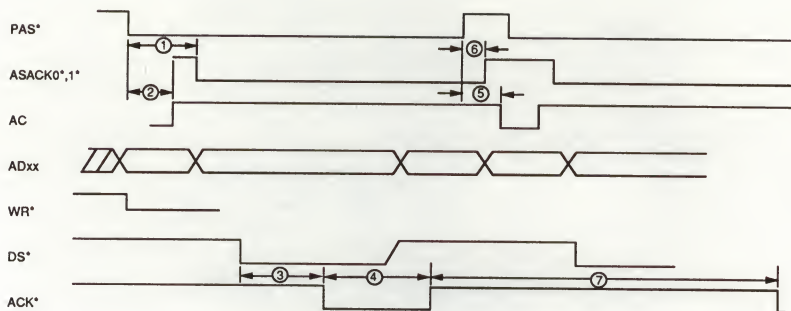


FIGURE 3-5. VSB WRITE CYCLE TIMING

No.	Parameter	Min	Typ	Max	Unit	Notes
1	PAS* low to ASACK0*/ASACK1* low	50	55	60	nsec	--
2	PAS* low to AC high	25	35	45	nsec	--
3	DS* low to ACK* low	60	75	385	nsec	1
4	DS* high to ACK* high	10	20	30	nsec	--
5	PAS* high to AC low	10	15	20	nsec	--
6	PAS* high to ASACK0*/ASACK1* high	15	20	25	nsec	--
7	ACK* low to ACK* high	--	240	480	nsec	1,2

Notes:

- 1) The maximum time can result if a refresh has just started when the board is selected.
- 2) Cycle time is dependent on handshakes and speed of master changing from address to data phases. These figures represent DS* low, 75 nsec after PAS* goes low, with ACK* low to DS* high = 10 nsec, DS* high to ACK* high = 15 nsec, and ACK* high to PAS* low = 30 nsec.

3.4 VMEbus INTERFACE

The VMEbus interface is one of two ports to the MVME224's DRAM array. The VMEbus interface receives address, data, and control from the VMEbus and provides access to the DRAM array and the Control and Status Register (CSR). It supports byte, word, and longword transfer and unaligned transfers. It responds to 24- or 32-bit addresses with the proper address modifier codes supplied. When responding to 24-bit address codes, the upper eight address lines are not considered. However, the upper eight address mapping

switches must be mapped to 0 (closed). Therefore, with 24-bit addressing, the module cannot be decoded higher than 00FFFFFF. It supports 16- or 32-bit data transfers. The address modifier codes are decoded in PAL U99, which can be changed to support unique user requirements. It may be mapped to be decoded on any 1-megabyte boundary in the addressing range. It does not support block transfer on the VMEbus.

3.5 VSB INTERFACE

The VSB interface is one of two ports to the MVME224's DRAM array. The VSB interface receives address, data and control information from the VSB bus and provides access to the DRAM array. It is a 32-bit address bus and supports byte, word, and longword transfers including unaligned transfers. It does support block transfers up to one megabyte.

3.6 CONTROL AND STATUS REGISTER

The Control/Status Register provides a VMEbus accessible register for MVME224 status and control. This register is writable and readable from the VMEbus. The Control/Status Register has three bits which are defined in the following text.

LD07	LD06	LD05	LD04	LD03	LD02	LD01	LD00
PES	Not Used	Not Used	Not Used	Not Used	Not Used	WWP	EPD

EPD < Enable Parity Detection >

This bit, when set to a "1", allows parity error detection. It is used to enable or disable parity error detection. It is cleared (parity error detection disabled) on power up or reset. It is changed to a "1" when a "1" is written to this bit and cleared to a "0" when a "0" is written to this bit. When this bit is a "0", parity is still written according to the status of the Write Wrong Parity bit.

WWP < Write Wrong Parity >

This bit, when set to a "1", indicates that a parity error has occurred on this module on either the VMEbus or the VSB. It does not indicate that the last read was a parity error, but that a parity error has occurred since it was last cleared. It is in an undetermined state on power up or reset. It is cleared to a "0" when any write occurs to the Control/Status Register and changed to a "1" when a parity error is detected, whether parity is enabled or not.

< Parity Error Status>

This bit, when set to a "1", indicates that a parity error has occurred on this module on either the VMEbus or the VSB. It does not indicate that the last read was a parity error, but that a parity error has occurred since it was last cleared. It is cleared to a "0" on power up or reset or when any write occurs to the Control/Status Register and changed to a "1" when a parity error is detected, whether parity is enabled or not.

Parity is generated and checked on a byte wide basis. Parity is odd and is checked on each read and reported according to the state of the CSR Parity Enabled bit (bit 0) in the form of BERR* (VMEbus) or ERR* (VSB bus).

Addressing is independently selectable on the VMEbus and VSB bus on 1Mb boundaries. The CSR is mapped dependent on the mapping of the addressing to the RAM on the VMEbus (refer to section 3.9).

When mapping to different addresses on the VMEbus and VSB bus, it must be observed that the RAM on both buses at the same address is the same RAM location, even if they have different starting addresses. For example, if the VMEbus is mapped at 00000000 and the VSB bus is mapped at 00200000, the RAM at 00200000 will be the same RAM location on both buses. The RAM location on VME at 00000000 is not the same as the RAM location at 00200000 on the VSB bus. The following table provides the VME/VSB mapping.

S2 -4	S2 -3	S2 -2	S2 -1	S1 -8	S1 -7	S1 -6	S1 -5	S1 -4	S1 -3	S1 -2	S1 -1	VME Address	Mapping	Switches
S3 -8	S3 -7	S3 -6	S3 -5	S3 -4	S3 -3	S3 -2	S3 -1	S2 -8	S2 -7	S2 -6	S2 -5	VSBC Address	Mapping	Switches
												RAM	Address	In Hexadecimal
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0	1	0	0	0
0	0	0	0	0	0	0	0	0	0	1	0	0	0	0
0	0	0	0	0	0	0	0	0	0	1	1	0	0	0
0	0	0	0	0	0	0	0	0	1	0	0	0	0	0
0	0	0	0	0	0	0	0	0	1	0	1	0	0	0
0	0	0	0	0	0	0	0	0	1	1	0	0	0	0
0	0	0	0	0	0	0	0	0	1	1	1	0	0	0

TABLE 3-1. VME/VSB ADDRESS MAPPING (cont.)

S2 -4	S2 -3	S2 -2	S2 -1	S1 -8	S1 -7	S1 -6	S1 -5	S1 -4	S1 -3	S1 -2	S1 -1	VME Address Mapping Switches
S3 -8	S3 -7	S3 -6	S3 -5	S3 -4	S3 -3	S3 -2	S3 -1	S2 -8	S2 -7	S2 -6	S2 -5	VSB Address Mapping Switches
RAM Address In Hexadecimal												
0	0	0	0	0	0	0	0	1	0	0	0	0 0 8 0 0 0 0 0
0	0	0	0	0	0	0	0	1	0	0	1	0 0 9 0 0 0 0 0
0	0	0	0	0	0	0	0	1	0	1	0	0 0 A 0 0 0 0 0
0	0	0	0	0	0	0	0	1	0	1	1	0 0 B 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	0	0 0 C 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	1	0 0 D 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	0	0 0 E 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	1	0 0 F 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	0	0	0 1 0 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	0	1	0 1 1 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	0	1	0 1 2 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	0	1	0 1 3 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	1	0	0 1 4 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	1	0	0 1 5 0 0 0 0 0
0	0	0	0	0	0	0	0	0	0	1	1	0 1 6 0 0 0 0 0
0	0	0	0	0	0	0	0	0	1	1	1	0 1 7 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	0	0 1 8 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	1	0 1 9 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	1	0 1 A 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	0	1	0 1 B 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	0	0 1 C 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	0	0 1 D 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	1	0 1 E 0 0 0 0 0
0	0	0	0	0	0	0	0	1	1	1	1	0 1 F 0 0 0 0 0
0	0	0	0	0	0	0	1	0	0	0	0	0 2 0 0 0 0 0 0
0	0	0	0	0	0	1	0	0	0	0	0	0 4 0 0 0 0 0 0
0	0	0	0	1	0	0	0	0	0	0	0	0 8 0 0 0 0 0 0
0	0	0	1	0	0	0	0	0	0	0	0	1 0 0 0 0 0 0 0
0	0	1	0	0	0	0	0	0	0	0	0	2 0 0 0 0 0 0 0
0	1	0	0	0	0	0	0	0	0	0	0	4 0 0 0 0 0 0 0
1	0	0	0	0	0	0	0	0	0	0	0	8 0 0 0 0 0 0 0

FUNCTIONAL DESCRIPTION

3.9 CSR MAPPING

The following table provides the switch settings for the CSR address mapping.

TABLE 3-2. CSR ADDRESS MAPPING

S1 -7	S1 -6	S1 -5	S1 -4	S1 -3	S1 -2	CSR Address	RAM Addresses
0	0	0	0	0	0	BE01	X00XXXXX, X01XXXXX, X80XXXXX, X81XXXXX
0	0	0	0	0	1	BE05	X02XXXXX, X03XXXXX, X82XXXXX, X83XXXXX
0	0	0	0	1	0	BE09	X04XXXXX, X05XXXXX, X84XXXXX, X85XXXXX
0	0	0	0	1	1	BE0D	X06XXXXX, X07XXXXX, X86XXXXX, X87XXXXX
0	0	0	1	0	0	BE11	X08XXXXX, X09XXXXX, X88XXXXX, X89XXXXX
0	0	0	1	0	1	BE15	X0AXXXXX, X0BXXXXX, X8AXXXXX, X8BXXXXX
0	0	0	1	1	0	BE19	X0CXXXXX, X0DXXXXX, X8CXXXXX, X8DXXXXX
0	0	0	1	1	1	BE1D	X0EXXXXX, X0FXXXXX, X8EXXXXX, X8FXXXXX
0	0	1	0	0	0	BE21	X10XXXXX, X11XXXXX, X90XXXXX, X91XXXXX
0	0	1	0	0	1	BE25	X12XXXXX, X13XXXXX, X92XXXXX, X93XXXXX
0	0	1	0	1	0	BE29	X14XXXXX, X15XXXXX, X94XXXXX, X95XXXXX
0	0	1	0	1	1	BE2D	X16XXXXX, X17XXXXX, X96XXXXX, X97XXXXX
0	0	1	1	0	0	BE31	X18XXXXX, X19XXXXX, X98XXXXX, X99XXXXX
0	0	1	1	0	1	BE35	X1AXXXXX, X1BXXXXX, X9AXXXXX, X9BXXXXX
0	0	1	1	1	0	BE39	X1CXXXXX, X1DXXXXX, X9CXXXXX, X9DXXXXX
0	0	1	1	1	1	BE3D	X1EXXXXX, X1FXXXXX, X9EXXXXX, X9FXXXXX
0	1	0	0	0	0	BE41	X20XXXXX, X21XXXXX, XA0XXXXX, XA1XXXXX
0	1	0	0	0	1	BE45	X22XXXXX, X23XXXXX, XA2XXXXX, XA3XXXXX
0	1	0	0	1	0	BE49	X24XXXXX, X25XXXXX, XA4XXXXX, XA5XXXXX
0	1	0	0	1	1	BE4D	X26XXXXX, X27XXXXX, XA6XXXXX, XA7XXXXX
0	1	0	1	0	0	BE51	X28XXXXX, X29XXXXX, XA8XXXXX, XA9XXXXX
0	1	0	1	0	1	BE55	X2AXXXXX, X2BXXXXX, XAAXXXXX, XABXXXXX
0	1	0	1	1	0	BE59	X2CXXXXX, X2DXXXXX, XACXXXXX, XADXXXXX
0	1	0	1	1	1	BE5D	X2EXXXXX, X2FXXXXX, XAEXXXXX, XAFXXXXX
0	1	1	0	0	0	BE61	X30XXXXX, X31XXXXX, XB0XXXXX, XB1XXXXX
0	1	1	0	0	1	BE65	X32XXXXX, X33XXXXX, XB2XXXXX, XB3XXXXX
0	1	1	0	1	0	BE69	X34XXXXX, X35XXXXX, XB4XXXXX, XB5XXXXX
0	1	1	0	1	1	BE6D	X36XXXXX, X37XXXXX, XB6XXXXX, XB7XXXXX
0	1	1	1	0	0	BE71	X38XXXXX, X39XXXXX, XB8XXXXX, XB9XXXXX
0	1	1	1	0	1	BE75	X3AXXXXX, X3BXXXXX, XBAXXXXX, XBBXXXXX
0	1	1	1	1	0	BE79	X3CXXXXX, X3DXXXXX, XBCXXXXX, XBDXXXXX
0	1	1	1	1	1	BE7D	X3EXXXXX, X3FXXXXX, XBEXXXXX, XBFXXXXX
1	0	0	0	0	0	BE81	X40XXXXX, X41XXXXX, XC0XXXXX, XC1XXXXX
1	0	0	0	0	1	BE85	X42XXXXX, X43XXXXX, XC2XXXXX, XC3XXXXX
1	0	0	0	1	0	BE89	X44XXXXX, X45XXXXX, XC4XXXXX, XC5XXXXX

TABLE 3-2. CSR ADDRESS MAPPING (cont.)

S1 -7	S1 -6	S1 -5	S1 -4	S1 -3	S1 -2	CSR Address	RAM Addresses
1	0	0	0	1	1	BE8D	X46XXXXX, X47XXXXX, XC6XXXXX, XC7XXXXX
1	0	0	1	0	0	BE91	X48XXXXX, X49XXXXX, XC8XXXXX, XC9XXXXX
1	0	0	1	0	1	BE95	X4AXXXXX, X4BXXXXX, XCAXXXXX, XCBXXXXX
1	0	0	1	1	0	BE99	X4CXXXXX, X4DXXXXX, XCCXXXXX, XCDXXXXX
1	0	0	1	1	1	BE9D	X4EXXXXX, X4FXXXXX, XCEXXXXX, XCFXXXXX
1	0	1	0	0	0	BEA1	X50XXXXX, X51XXXXX, XD0XXXXX, XD1XXXXX
1	0	1	0	0	1	BEA5	X52XXXXX, X53XXXXX, XD2XXXXX, XD3XXXXX
1	0	1	0	1	0	BEA9	X54XXXXX, X55XXXXX, XD4XXXXX, XD5XXXXX
1	0	1	0	1	1	BEAD	X56XXXXX, X57XXXXX, XD6XXXXX, XD7XXXXX
1	0	1	1	0	0	BEB1	X58XXXXX, X59XXXXX, XD8XXXXX, XD9XXXXX
1	0	1	1	0	1	BEB5	X5AXXXXX, X5BXXXXX, XDAXXXXX, XDBXXXXX
1	0	1	1	1	0	BEB9	X5CXXXXX, X5DXXXXX, XDCXXXXX, XDDXXXXX
1	0	1	1	1	1	BEBD	X5EXXXXX, X5FXXXXX, XDEXXXXX, XDFXXXXX
1	1	0	0	0	0	BEC1	X60XXXXX, X61XXXXX, XE0XXXXX, XE1XXXXX
1	1	0	0	0	1	BEC5	X62XXXXX, X63XXXXX, XE2XXXXX, XE3XXXXX
1	1	0	0	1	0	BEC9	X64XXXXX, X65XXXXX, XE4XXXXX, XE5XXXXX
1	1	0	0	1	1	BECD	X66XXXXX, X67XXXXX, XE6XXXXX, XE7XXXXX
1	1	0	1	0	0	BED1	X68XXXXX, X69XXXXX, XE8XXXXX, XE9XXXXX
1	1	0	1	0	1	BED5	X6AXXXXX, X6BXXXXX, XEAXXXXX, XEBXXXXX
1	1	0	1	1	0	BED9	X6CXXXXX, X6DXXXXX, XECXXXXX, XEDXXXXX
1	1	0	1	1	1	BEDD	X6EXXXXX, X6FXXXXX, XEEXXXXX, XEFXXXXX
1	1	1	0	0	0	BEE1	X70XXXXX, X71XXXXX, XF0XXXXX, XF1XXXXX
1	1	1	0	0	1	BEE5	X72XXXXX, X73XXXXX, XF2XXXXX, XF3XXXXX
1	1	1	0	1	0	BEE9	X74XXXXX, X75XXXXX, XF4XXXXX, XF5XXXXX
1	1	1	0	1	1	BEED	X76XXXXX, X77XXXXX, XF6XXXXX, XF7XXXXX
1	1	1	1	0	0	BEF1	X78XXXXX, X79XXXXX, XF8XXXXX, XF9XXXXX
1	1	1	1	0	1	BEF5	X7AXXXXX, X7BXXXXX, XFAXXXXX, XFBXXXXX
1	1	1	1	1	0	BEF9	X7CXXXXX, X7DXXXXX, XFCXXXXX, XFDXXXXX
1	1	1	1	1	1	BEFD	X7EXXXXX, X7FXXXXX, XFEXXXXX, XFFXXXXX

Switch settings 0 = closed, 1 = open.

CSR Addresses are in Short I/O address space.

RAM address - X = don't care.

FUNCTIONAL DESCRIPTION

3

CHAPTER 4 - SUPPORT INFORMATION

4.1 INTRODUCTION

This chapter provides the connector pin signal descriptions, parts list, parts location diagram, and the schematic diagram for the MVME224-1/-2 memory modules.

4.2 INTERCONNECT SIGNALS

The MVME224-1/-2 memory modules use the P1 and P2 backplane connectors to interconnect with VMEbus and to power the board. The P1 and P2 connectors are described in the following sections.

4.2.1 P1 Connector

The P1 connector is used to interconnect with the main body of VMEbus signals. It is a standard DIN, triple row, 96-pin male connector. The pin connections, VMEbus signal mnemonics, and signal descriptions for the P1 connector are provided in Table 4-1. Refer to the VMEbus Specification (Rev C.1) for a complete description of the VMEbus signals.

TABLE 4-1. CONNECTOR P1 INTERCONNECT SIGNALS

Pin Number	Signal Mnemonic	Signal Name and Description
A1-A8	D00-D07	DATA BUS (bits 0-7) - Eight of 16 three-state bidirectional data bus signals on P1.
A9	GND	GROUND
A10	NC	NOT CONNECTED
A11	GND	GROUND
A12	DS1*	DATA STROBE 1 - A three-state driven signal that enables a data transfer with the slave. It indicates for byte/word transfers that the data transfer will occur on data bus signals D08 through D15.
A13	DS0*	DATA STROBE 0 - A three-state driven signal that enables a data transfer with the slave. It indicates for byte/word transfers that the data transfer will occur on data bus signals D00 through D07.

SUPPORT INFORMATION

TABLE 4-1. CONNECTOR P1 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
A14	WRITE*	WRITE ENABLE - A three state driven signal that indicates the data transfer is a write cycle to the slave when asserted, or a read cycle from the slave when not asserted.
A15	GND	GROUND
A16	DTACK*	DATA TRANSFER ACKNOWLEDGE - An open-collector signal driven by the slave. A falling edge indicates that the slave has driven valid data on the data bus during a read cycle, or that the slave has received valid data from the data bus during a write cycle. A low level also indicates the slave may be active on the data bus.
A17	GND	GROUND
A18	AS*	ADDRESS STROBE - A three-state driven signal whose falling edge indicates a valid address is on the address bus. A low level also indicates ownership of VMEbus and the slave resource.
A19	GND	GROUND
A20	IACK*	INTERRUPT ACKNOWLEDGE - A three-state driven signal that indicates an interrupt acknowledge cycle.
A21	IACKIN*	(INTERRUPT) ACKNOWLEDGE INPUT - The IACKIN* and IACKOUT* signals form an interrupt acknowledge daisy-chain to select the interrupting device to supply an interrupt vector. IACKIN* is connected to IACKOUT*.
A22	IACKOUT*	(INTERRUPT) ACKNOWLEDGE OUTPUT - The IACKIN* and IACKOUT* signals form an interrupt acknowledge daisy-chain to select the interrupting device to supply an interrupt vector. IACKOUT* is connected to IACKIN*.
A23	AM4	ADDRESS MODIFIER (bit 4) - One of six three-state driven signals that specify information about the bus cycle including address size and cycle type.

TABLE 4-1. CONNECTOR P1 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
A24-A30	A07-A01	ADDRESS BUS (bits 7-1, reverse ordered) - Seven of 23 three-state driven address bus signals on P1. The extended 8 signals of the address bus are on connector P2.
A31	-12V	-12 Vdc POWER
A32	+5V	+5 Vdc POWER
B1-B03	NC	NOT CONNECTED
B4	BG0IN*	BUS GRANT 0 IN - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. The remaining three bus-grant-in lines are connected directly to their respective bus-grant-out lines.
B5	BG0OUT*	BUS GRANT 0 OUT - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. The remaining three bus-grant-out lines are connected directly to their respective bus-grant-in lines.
B6	BG1IN*	BUS GRANT 1 IN - Same as BG0IN on pin B4.
B7	BG1OUT*	BUS GRANT 1 OUT - Same as BG0OUT on pin B5.
B8	BG2IN*	BUS GRANT 2 IN - Same as BG0IN on pin B4.
B9	BG2OUT*	BUS GRANT 2 OUT - Same as BG0OUT on pin B5.
B10	BG3IN*	BUS GRANT 3 IN - Same as BG0IN on pin B4.
B11	BG3OUT*	BUS GRANT 3 OUT - Same as BG0OUT on pin B5.
B12-B15	BR0*-BR3*	BUS REQUEST (bits 0-3) - The bus request lines are open-collector signals generated by requesters. A low level on one of these lines indicates that some master needs to use the DTB.
B16-B19	AM0-AM3	ADDRESS MODIFIER (bits 0-3) - Same as pin A23.
B20	GND	GROUND
B21,B22	(reserved)	NOT CONNECTED
B23	GND	GROUND

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TABLE 4-1. CONNECTOR P1 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
B24-B30	IRQ7*-IRQ1*	INTERRUPT REQUEST (bits 7-1, reverse ordered) - Seven open-collector signals used to request interrupt servicing.
B31	NC	NOT CONNECTED
B32	+5V	+5 Vdc POWER
C1-C8	D08-D15	DATA BUS (bits 8-15) - Same as pins A0 through A8.
C9	GND	GROUND
C10	NC	NOT CONNECTED
C11	BERR*	BUS ERROR - An active low output signal that indicates an error has occurred during a data transfer cycle.
C12	SYSRESET*	SYSTEM RESET - An open-collector signal which, when low, causes the system to be reset.
C13	LWORD*	LONGWORD - A three-state driven signal that indicates the data transfer is a longword (32-bit transfer) aligned operation. When not asserted, it indicates a byte or word operation.
C14	AM5	ADDRESS MODIFIER 5 - Same as AM4 on pin A23.
C15-C30	A23-A08	ADDRESS BUS (bits 23-08, reverse ordered) - Sixteen of 23 three-state driven address bus signals on P1. The extended 8 signals of the address bus are on connector P2.
C31	NC	NOT CONNECTED
C32	+5V	+5 Vdc POWER

4.2.2 P2 Connector

The P2 connector is used to interconnect with the extended sections of the address and data busses on the VMEbus, the VSB bus, and to additional power and ground pins. Connector P2 is a standard DIN, triple row, 96-pin male connector. Table 4-2 provides the pin connections, signal mnemonics, and signal descriptions. Refer to the VMEbus Specification (Rev C.1) for a complete description of VMEbus signals.

TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS

Pin Number	Signal Mnemonic	Signal Name and Description
A1	AD00	(VSB) ADDRESS/DATA BUS (bit 00) - One of 32 multiplexed address/data lines that are controlled by the three-state drivers on the master and slave devices. These lines are all active high, TTL three-state signals.
A2	AD02	(VSB) ADDRESS/DATA BUS (bit 02) - Same as AD00 on pin A1.
A3	AD04	(VSB) ADDRESS/DATA BUS (bit 04) - Same as AD00 on pin A1.
A4	AD06	(VSB) ADDRESS/DATA BUS (bit 06) - Same as AD00 on pin A1.
A5	AD08	(VSB) ADDRESS/DATA BUS (bit 08) - Same as AD00 on pin A1.
A6	AD10	(VSB) ADDRESS/DATA BUS (bit 10) - Same as AD00 on pin A1.
A7	AD12	(VSB) ADDRESS/DATA BUS (bit 12) - Same as AD00 on pin A1.
A8	AD14	(VSB) ADDRESS/DATA BUS (bit 14) - Same as AD00 on pin A1.
A9	AD16	(VSB) ADDRESS/DATA BUS (bit 16) - Same as AD00 on pin A1.
A10	AD18	(VSB) ADDRESS/DATA BUS (bit 18) - Same as AD00 on pin A1.

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TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
A11	AD20	(VSB) ADDRESS/DATA BUS (bit 20) - Same as AD00 on pin A1.
A12	AD22	(VSB) ADDRESS/DATA BUS (bit 22) - Same as AD00 on pin A1.
A13	AD24	(VSB) ADDRESS/DATA BUS (bit 24) - Same as AD00 on pin A1.
A14	AD26	(VSB) ADDRESS/DATA BUS (bit 26) - Same as AD00 on pin A1.
A15	AD28	(VSB) ADDRESS/DATA BUS (bit 28) - Same as AD00 on pin A1.
A16	AD30	(VSB) ADDRESS/DATA BUS (bit 30) - Same as AD00 on pin A1.
A17	GND	GROUND
A18	NC	NOT CONNECTED
A19	DS*	(VSB) DATA STROBE - The falling edge of DS* indicates that a valid data transfer will occur over AD00 through AD31. During write cycles, write data is valid at the falling edge of DS*. This line is an active low, TTL three-state signal.
A20	WR*	(VSB) WRITE - This signal, when low, indicates that a write operation is to be performed and when high, indicates that a read operation will occur. WR* is valid when AS* is asserted on the bus. Line WR* is a TTL, three-state signal.
A21	SPACE0	SPACE SELECT (bit 0) - One of two lines that are driven by the active master with a space code. They are used to select one of three address spaces, or to initiate an (interrupt) ACK* or an arbitration cycle.
A22	SPACE1	SPACE SELECT (bit 1) - Same as SPACE0 on pin A21.

TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
A23	LOCK	(VSB) BUS LOCK - This signal, when low, indicates the bus is locked and that no other master can obtain possession of the bus. LOCK* is also used in certain modes to indicate that a block transfer cycle is in progress. LOCK* is an active low, TTL three-state signal.
A24	ERR*	(VSB) BUS ERROR - This signal, when low, is issued by the selected slave module to indicate a fault condition while attempting a data transfer operation. This would typically be the result of a parity error detected on a slave device. Line ERR* is an active low, TTL open-collector signal.
A25-A27	GND	GROUND
A28-A30	NC	NOT CONNECTED
A31	BGIN*	(VSB) BUS GRANT IN - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. Connected directly to BGOUT*.
A32	NC	NOT CONNECTED
B1	+5V	+5 Vdc POWER
B2	GND	GROUND
B3	VMELOCK*	VMEbus LOCK - This signal, when low, indicates that the bus is in the middle of a multiple-cycle access and that any other bus should be excluded from shared memory.
B4-B11	A24-A31	ADDRESS BUS (bits 24-31) - Eight three-state driven address bus signals that form the extended section of the address bus. The standard 23 signals of the address bus are on connector P1.
B12	GND	GROUND
B13	+5V	+5 Vdc POWER

SUPPORT INFORMATION

TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
B14-B21	D16-D23	DATA BUS (bits 17-23) - Eight of 16 bidirectional three-state driven data lines which provide the expanded data path between the data transfer bus master and slave.
B22	GND	GROUND
B23-B30	D24-D31	DATA BUS (bits 24-31) - Same as D16 through D23 on pins B14 through B21.
B31	GND	GROUND
B32	+5V	+5 Vdc POWER
C1	AD01	(VSB) ADDRESS/DATA BUS (bit 01) - Same as AD00 on pin A1.
C2	AD03	(VSB) ADDRESS/DATA BUS (bit 03) - Same as AD00 on pin A1.
C3	AD05	(VSB) ADDRESS/DATA BUS (bit 05) - Same as AD00 on pin A1.
C4	AD07	(VSB) ADDRESS/DATA BUS (bit 07) - Same as AD00 on pin A1.
C5	AD09	(VSB) ADDRESS/DATA BUS (bit 09) - Same as AD00 on pin A1.
C6	AD11	(VSB) ADDRESS/DATA BUS (bit 11) - Same as AD00 on pin A1.
C7	AD13	(VSB) ADDRESS/DATA BUS (bit 13) - Same as AD00 on pin A1.
C8	AD15	(VSB) ADDRESS/DATA BUS (bit 15) - Same as AD00 on pin A1.
C9	AD17	(VSB) ADDRESS/DATA BUS (bit 17) - Same as AD00 on pin A1.
C10	AD19	(VSB) ADDRESS/DATA BUS (bit 19) - Same as AD00 on pin A1.

TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
C11	AD21	(VSB) ADDRESS/DATA BUS (bit 21) - Same as AD00 on pin A1.
C12	AD23	(VSB) ADDRESS/DATA BUS (bit 23) - Same as AD00 on pin A1.
C13	AD25	(VSB) ADDRESS/DATA BUS (bit 25) - Same as AD00 on pin A1.
C14	AD27	(VSB) ADDRESS/DATA BUS (bit 27) - Same as AD00 on pin A1.
C15	AD29	(VSB) ADDRESS/DATA BUS (bit 29) - Same as AD00 on pin A1.
C16	AD31	(VSB) ADDRESS/DATA BUS (bit 31) - Same as AD00 on pin A1.
C17-C20	GND	GROUND
C21	SIZE0*	(VSB) BUS SIZE (bit 0) - One of two lines that in conjunction with address A00, determines the active portion of the data bus. This line is an active low, TTL three-state signal.
C22	PAS*	(VSB) ADDRESS STROBE - The falling edge of PAS* indicates that a valid address is present on the AD00 through AD31 bus. This line is an active low, TTL three-state signal.
C23	SIZE1*	(VSB) BUS SIZE (bit 1) - Same as SIZE0 on pin C21.
C24	GND	GROUND
C25	ACK*	(VSB) DATA TRANSFER ACKNOWLEDGE - This signal is issued by a slave device to complete the handshake for a data transfer operation. This line is an active low, TTL open-collector signal.
C26	AC	(VSB) ADDRESS DECODE COMPLETE - This signal is issued by a slave device to indicate that address decoding has been completed. All slave devices must allow AC (Address Decode Complete) to go high after the decode interval has elapsed regardless

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TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
		whether the device is selected by the current address on the bus. This line is an active high, TTL open-collector signal.
C27	ASACK1*	(VSB) ADDRESS/SIZE ACKNOWLEDGE (bit 1) - One of two lines that are driven by the VSB slave devices and are used to perform several functions. The slave device that is selected by the address decoding must drive at least one ASACK* signal to control switching the multiplexed address/data bus from address to data. Secondly, both are encoded to indicate to the master the size of the data bus for the slave module. Finally, ASACK* can be gated with the signal AC (Address Decode Complete) on the master device. The condition of AC active and ASACK* inactive, while AS* is asserted, is defined to indicate that no VSB slave module has decoded the address being driven at that time, or that there are no VSB slave modules installed. This provides the VSB master the opportunity to switch to the VMEbus when VSB slaves are not responding. ASACK0* and ASACK1* are active low, TTL open-collector signals.
C28	ASACK0*	(VSB) ADDRESS/SIZE ACKNOWLEDGE (bit 0) - Same as ASACK1* on pin C27.
C29	CACHE*	(VSB) CACHEABLE - CACHE* is issued by a slave device at the same time that ASACK0* and ASACK1* are issued to indicate that the current transfer is cacheable. CACHE* remains inactive to indicate that the transfer is non-cacheable. This line is an active low, TTL open-collector signal.
C30	WAIT*	(VSB) HOLD THIS CYCLE - This signal is an output line used in conjunction with the signals AC. If this line is driven low at the beginning of a cycle, addresses must remain stable and DS* cannot be driven until AC goes high. Also, data must remain valid along with DS* during the data transfer portion of the cycle until WAIT* is negated. This signal is an active low TTL open-collector signal.

TABLE 4-2. CONNECTOR P2 INTERCONNECT SIGNALS (cont.)

Pin Number	Signal Mnemonic	Signal Name and Description
C31	NC	NOT CONNECTED (on MVME224).
C32	BGOUT*	(VSB) BUS GRANT OUT - Bus-grant-in and bus-grant-out form a daisy-chained bus grant. Connected directly to BGIN*.

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4.3 PARTS LIST

The parts location diagram for the MVME224 is provided in Figure 4-1. The reference designation, part number, and description for each component are listed in Table 4-3. This parts list reflects the latest issue of the MVME224 hardware at the time of the release of this user's manual.

TABLE 4-3. MVME224 PARTS LIST

Reference Designation	Motorola Part Number	Description
--	84-W8500B01B	Printed wiring board assembly, MVME224-2
C1-10, C13-21, C24-37, C40-51	21NW9632A03	Capacitor, ceramic, axial, .1MF, 50 Vdc
C11	21NW9604A58	Capacitor, ceramic, radial, 330pF, 50 Vdc
C12	21SW992C014	Capacitor, ceramic, .010MF, 50 Vdc
C22,C23, C38,C39	23NW9618A82	Capacitor, electrolytic, radial, 22MF, 25 Vdc
DL1	01NW9804C80	Delay module, 100 nsec
DL2	01NW9804C33	Delay module, 40 nsec
DL3	51NW9615W26	IC, DS1000M-100
DL4-6	51NW9615W46	IC, DS1000M-50
DS1,DS2	48NW9612A59	LED, green, right-angle
J1,J3	29NW9805B44	Jumper, 2-pin (2 req'd)[used at J1(1-2),J3(1-2)]
J2	29NW9805C07	Pin, 0.025-inch square, gold, autoinsert (6 req'd)[used at J2(1-2),J4(1-2),J5(1-2)]
P1,P2	28NW9802E51	Connector, 96-pin, plug, PWB
--	05NW9007A26	Eyelet, 0.089-inch OD x 0.344-inch long (4 req'd)(used with P1 and P2)
R1,R2	06SW-124A29	Resistor, film, 1/8W, 5%, 150 ohms

TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
R3,R4,R7, R8,R10	51NW9626A37	Resistor network, SIP, four 33 ohms (for MVME224-1 version only)
R3,R4, R7-R10, R12-14	51NW9626A37	Resistor network, SIP, four 33 ohms (for MVME224-2 version only)
R5	51NW9626A49	Resistor network, SIP, seven 10K ohms
R6,R15, R16-21	51NW9626B56	Resistor network, SIP, nine 10K ohms
R11	06SW-124A81	Resistor, film, 1/8W, 5%, 22K ohms
R22	51NW9626B47	Resistor network, SIP, nine 22K ohms
S1-3	40NW9801A34	Switch, DIP, SPST, 8-position
U1	51NW9615K47	IC, 74F244PC
U2-19, U27-44	51NW9615U44	IC, M5M4C1000L-10 (for MVME224-1 version only)
U2-19, U27-44, U52-69, U76-93	51NW9615U44	IC, M5M4C1000L-10 (for MVME224-2 version only)
U20,U45, U70	51NW9615K60	IC, 74F158APC
U23,U24 U122,U123, U134,U135, U148,U149	51NW9615R36	IC, 74F543SPC
U25	(NOTE)	IC, programmed
--	09NW9811B01	Socket, IC, DIL, 24-pin (1 req'd)(used at U25)
U26	(NOTE)	IC, programmed (for MVME224-1 version only)

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TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
U26	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U26)
U46	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U46)
U47	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U47)
U48	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U48)
U49,U74, U75,U121, U132,U133	51NW9615K99	IC, 74F374PC
U5Ø	51NW9615B65	IC, MC1455P1
U72	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U72)
U73	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U73)
U95,U145, U146	51NW9615F85	IC, SN74S38N
U96	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U96)

TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
U97	(NOTE)	IC, programmed (for MVME224-1 version only)
U97	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U97)
U98	(NOTE)	IC, programmed (for MVME224-1 version only)
U98	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U98)
U99	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U99)
U1ØØ	51NW9615R16	IC, SN74ALSØ4AN
U1Ø1	(NOTE)	IC, programmed (for MVME224-1 version only)
U1Ø1	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U1Ø1)
U1Ø2,U1Ø4	51NW9615K18	IC, 74F373PC
U1Ø3,U1Ø5	51NW9615W31	IC, SN74AS841NT
U1Ø6,U1Ø7	51NW9615M9Ø	IC, 74F245PC
U1Ø8,U1Ø9, U119,U12Ø	51NW9615V91	IC, SN74AS28ØN
U11Ø	51NW9615K65	IC, 74F64PC

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TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
U111	51NW9615K66	IC, 74F32PC
U112	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U112)
U113	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U113)
U114	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U114)
U115	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U115)
U116	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U116)
U117	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U117)
U118	(NOTE)	IC, programmed
--	Ø9NW9811A78	Socket, IC, DIL, 2Ø-pin (1 req'd)(used at U118)
U124	51NW9615K71	IC, 74FØ4PC
U125	51NW9615K67	IC, 74F2ØPC
U126-13Ø, U138	51NW9615J39	IC, 74F74PC

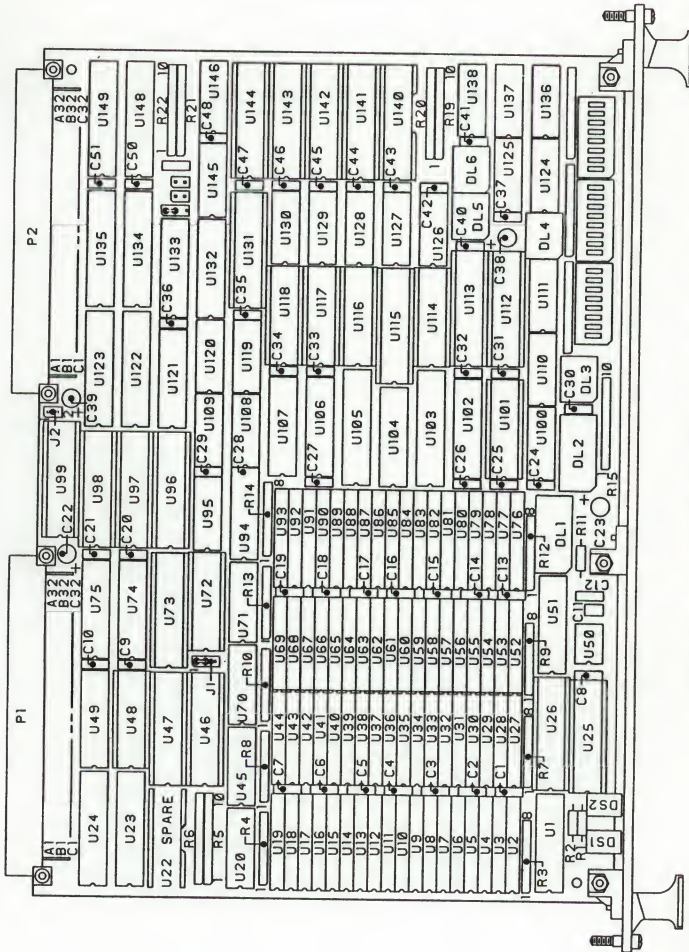
TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
U131	(NOTE)	IC, programmed (for MVME224-1 version only)
U131	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U131)
U136	51NW9615K7Ø	IC, 74FØ8PC
U137	51NW9615K73	IC, 74FØØPC
U139	(NOTE)	IC, programmed
--	Ø9-W4659B12	Socket, IC, SIL, 12-pin (2 req'd)(used at U139)
U14Ø	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U14Ø)
U141	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U141)
U142	(NOTE)	IC, programmed (for MVME224-1 version only)
U142	(NOTE)	IC, programmed (for MVME224-2 version only)
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U142)
U143	(NOTE)	IC, programmed
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U143)
U144	(NOTE)	IC, programmed

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TABLE 4-3. MVME224 PARTS LIST (cont.)

Reference Designation	Motorola Part Number	Description
--	Ø9NW9811BØ1	Socket, IC, DIL, 24-pin (1 req'd)(used at U144)
U147	(NOTE)	IC, programmed
--	Ø9-W4659B1Ø	Socket, IC, SIL, 1Ø-pin (2 req'd)(used at U147)
--	67NW9415A17	Kit, ejector handle, 6U component
--	64-W55Ø1BØ1A	Panel, front, MVME224-1,2
--	33-W5Ø89BØ1	Nameplate, Scanbe, logo
--	33-W5478BØ1	Nameplate, MVME224-1 (for MVME224-1 version only)
--	33-W5537BØ1	Nameplate, MVME224-2 (for MVME224-2 version only)
--	42NW94Ø1B14	Captive collar screw (2 req'd)
--	Ø3NW9ØØ4B48	Screw, captive, M2.5 (2 req'd)
NOTE: When ordering, use the number labeled on the part.		



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4.4 SCHEMATIC DIAGRAMS

Figure 4-2 (25 sheets) contains detailed schematic diagrams of the internal circuitry comprising the MVME224. These schematic diagrams represent the latest design. Occasionally, minor component changes are made at the factory. Therefore, when replacing a component, always use the same value as the defective component even though the schematic diagram may indicate a different value or type.

U149	U21U22
S3	
R22	
P2	
J5	J3
DS2	
DL6	
CA1	
HIGHEST NUMBER USED	NOT USED
REFERENCE DESIGNATIONS	

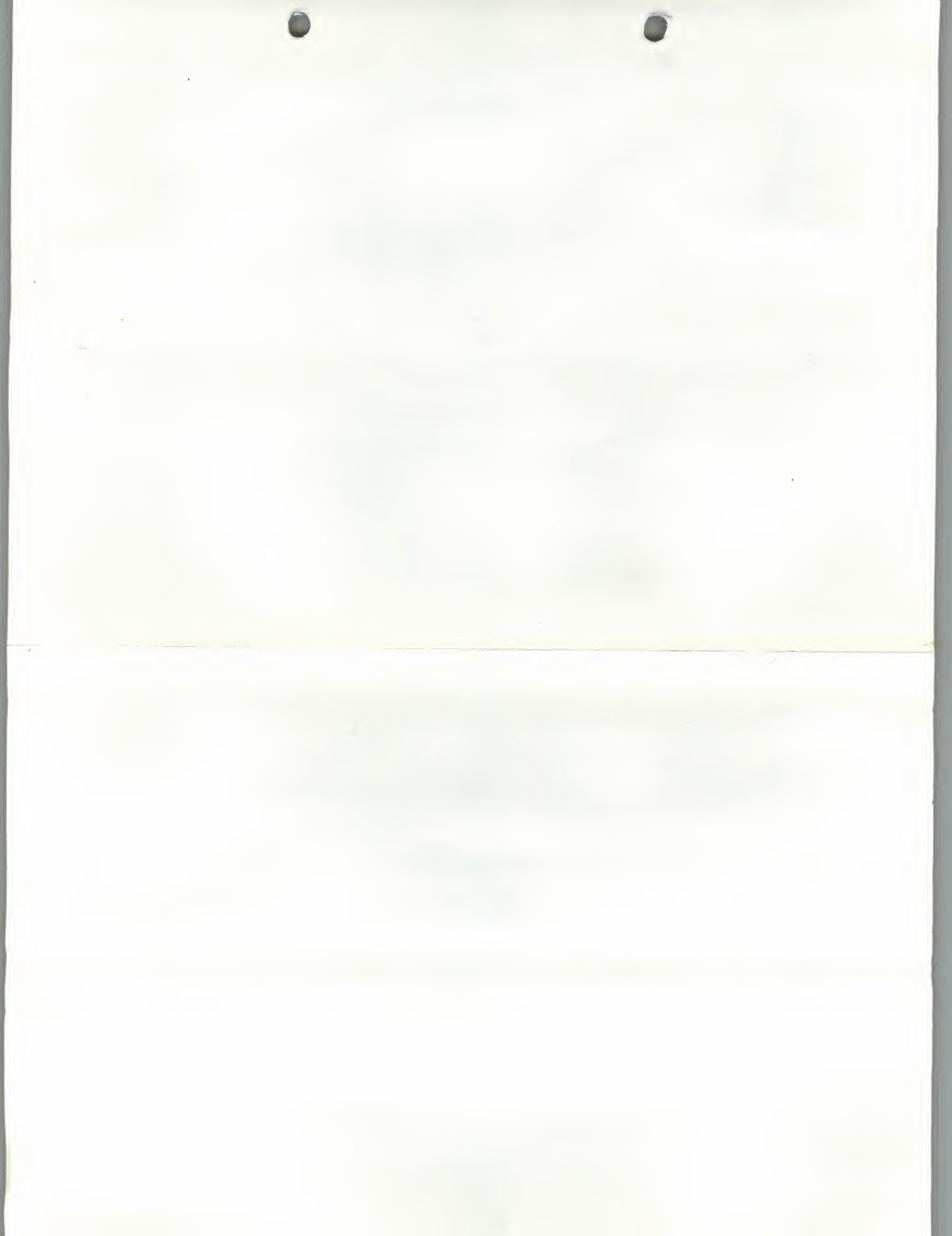
REF DES	TYPE	△	GND	+5V	SH
D11	100NS	7	14	14	
D12	100NS	7	14	14	
D13	100NS	4	8	14	
D14	50NS	4	8	10	
D15	50NS	4	8	7	
D16	50NS	4	8	10	
U1	74F244	10	24	14	
U2	MSM4CI000L	4	15	23	
U3	MSM4CI000L	4	15	23	
U4	MSM4CI000L	4	15	22	
U5	MSM4CI000L	4	15	22	
U6	MSM4CI000L	4	15	22	
U7	MSM4CI000L	4	15	22	
U8	MSM4CI000L	4	15	22	
U9	MSM4CI000L	4	15	22	
U10	MSM4CI000L	4	15	22	
U11	MSM4CI000L	4	15	22	
U12	MSM4CI000L	4	15	21	
U13	MSM4CI000L	4	15	21	
U14	MSM4CI000L	4	15	21	
U15	MSM4CI000L	4	15	21	
U16	MSM4CI000L	4	15	21	
U17	MSM4CI000L	4	15	21	
U18	MSM4CI000L	4	15	21	
U19	MSM4CI000L	4	15	21	
U20	74F158	8	16	18	
U23	74F543	12	24	6	
U24	74F543	12	24	6	
U25	PAL201.8	12	24	14	
U26	PAL201.8	12	24	14	
U27	MSM4CI000L	4	15	25	
U28	MSM4CI000L	4	15	25	
U29	MSM4CI000L	4	15	25	
U30	MSM4CI000L	4	15	22	
U31	MSM4CI000L	4	15	22	
U32	MSM4CI000L	4	15	22	
U33	MSM4CI000L	4	15	22	
U34	MSM4CI000L	4	15	22	
U35	MSM4CI000L	4	15	22	
U36	MSM4CI000L	4	15	22	
U37	MSM4CI000L	4	15	21	
U38	MSM4CI000L	4	15	21	
U39	MSM4CI000L	4	15	21	
U40	MSM4CI000L	4	15	21	
U41	MSM4CI000L	4	15	21	
U42	MSM4CI000L	4	15	21	
U43	MSM4CI000L	4	15	21	
U44	MSM4CI000L	4	15	21	
U45	74F158	8	16	18	
U46	PAL22V10	12	24	17	
U47	PAL22V10	12	24	17	
U48	PAL161.8	10	20	7	
U49	74F374	10	20	7	
U50	74F374	10	20	7	
U51	74F244	10	20	14	
U52	MSM4CI000L	4	15	23	
U53	MSM4CI000L	4	15	23	
U54	MSM4CI000L	4	15	23	

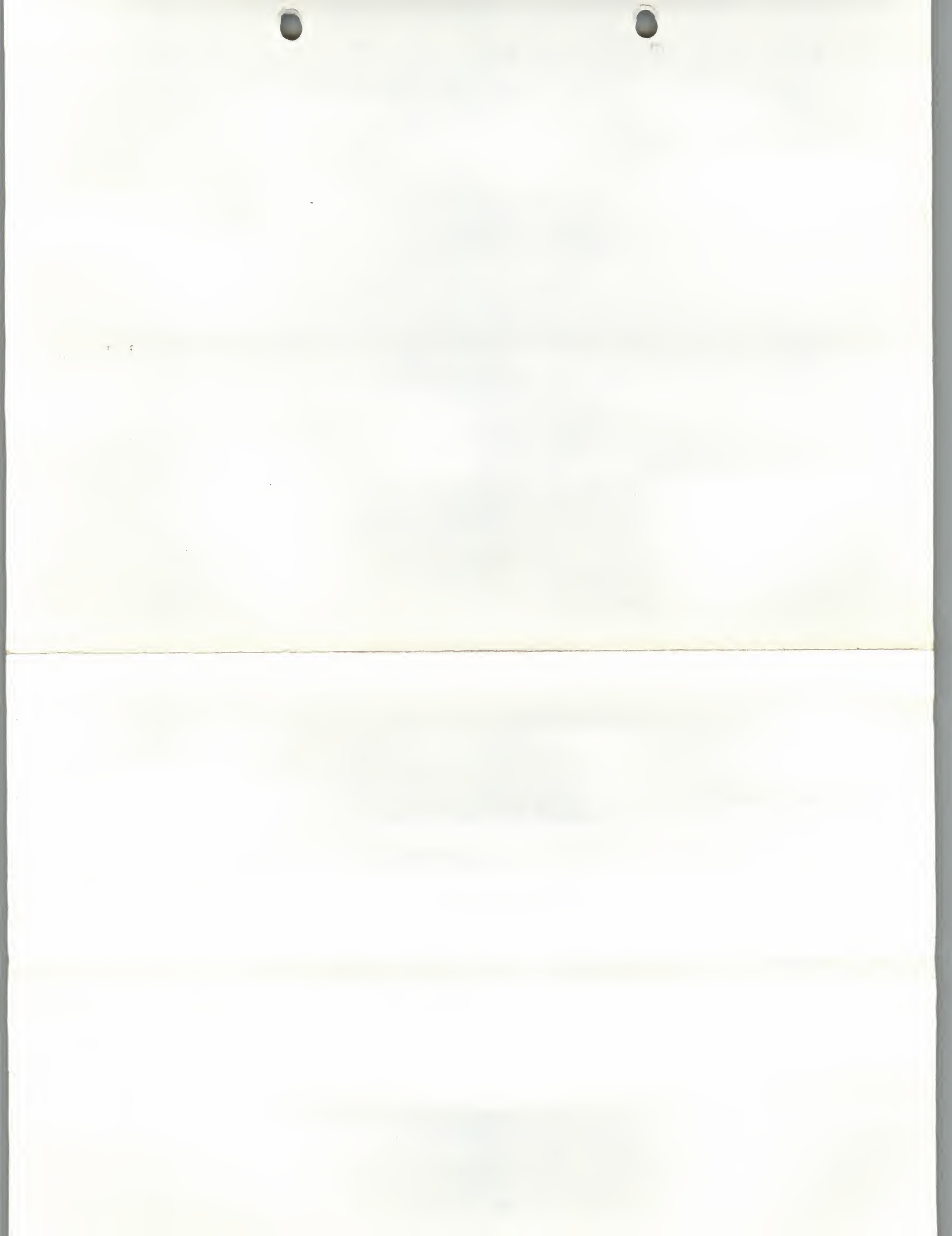
REF DES	TYPE	△	GND	+5V	SH
U55	MSM4CI000L	4	15	24	
U56	MSM4CI000L	4	15	24	
U57	MSM4CI000L	4	15	24	
U58	MSM4CI000L	4	15	24	
U59	MSM4CI000L	4	15	24	
U60	MSM4CI000L	4	15	24	
U61	MSM4CI000L	4	15	24	
U62	MSM4CI000L	4	15	23	
U63	MSM4CI000L	4	15	23	
U64	MSM4CI000L	4	15	23	
U65	MSM4CI000L	4	15	23	
U66	MSM4CI000L	4	15	23	
U67	MSM4CI000L	4	15	23	
U68	MSM4CI000L	4	15	23	
U69	MSM4CI000L	4	15	23	
U70	74F158	8	16	18	
U71	74F158	8	16	18	
U72	PAL161.8	10	20	17	
U73	PAL22V10	12	24	17	
U74	74F374	10	20	7	
U75	74F374	10	20	7	
U76	MSM4CI000L	4	15	25	
U77	MSM4CI000L	4	15	25	
U78	MSM4CI000L	4	15	24	
U79	MSM4CI000L	4	15	24	
U80	MSM4CI000L	4	15	24	
U81	MSM4CI000L	4	15	24	
U82	MSM4CI000L	4	15	24	
U83	MSM4CI000L	4	15	24	
U84	MSM4CI000L	4	15	24	
U85	MSM4CI000L	4	15	24	
U86	MSM4CI000L	4	15	23	
U87	MSM4CI000L	4	15	23	
U88	MSM4CI000L	4	15	23	
U89	MSM4CI000L	4	15	23	
U90	MSM4CI000L	4	15	23	
U91	MSM4CI000L	4	15	23	
U92	MSM4CI000L	4	15	23	
U93	MSM4CI000L	4	15	23	
U94	74F158	8	16	18	
U95	74F543	12	24	6	
U96	PAL22V10	12	24	8	
U97	PAL22V10	12	24	8	
U98	PAL22V10	12	24	8	
U99	PAL22V10	12	24	8	
U100	74F158	8	16	18	
U101	PAL161.8	10	20	16	
U102	74F374	10	20	20	
U103	74F543	12	24	20	
U104	74F374	10	20	20	
U105	74F543	12	24	20	
U106	74F245	10	20	12	
U107	74F245	10	20	12	
U108	74F245	10	20	12	
U109	74F245	10	20	12	
U110	74F64	7	14	19	
U111	74F32	7	14	214	
U112	PAL22V10	12	24	16	
U113	PAL201.8	12	24	16	
U114	PAL161.8	10	20	16	

REF DES	TYPE	△	GND	+5V	SH
U115	PAL201.8	10	20	17	
U116	PAL161.8	10	20	15	
U117	PAL161.8	10	20	15	
U118	PAL161.8	10	20	15	
U119	74F543	12	24	19	
U120	74F543	12	24	19	
U121	74F543	12	24	19	
U122	74F543	12	24	9	
U123	74F543	12	24	9	
U124	74F543	12	24	9	
U125	74F543	12	24	9	
U126	74F543	12	24	9	
U127	74F543	12	24	9	
U128	74F543	12	24	9	
U129	74F543	12	24	9	
U130	74F543	12	24	9	
U131	PAL22V10	12	24	11	
U132	74F374	10	20	10	
U133	74F374	10	20	10	
U134	74F543	12	24	9	
U135	74F543	12	24	9	
U136	74F543	12	24	9	
U137	74F543	12	24	9	
U138	74F543	12	24	9	
U139	PAL201.8	12	24	13	
U140	PAL201.8	12	24	8	
U141	PAL201.8	12	24	11	
U142	PAL22V10	12	24	11	
U143	PAL22V10	12	24	11	
U144	PAL22V10	12	24	11	
U145	74F543	12	24	11	
U146	74F543	12	24	11	
U147	PAL161.8	10	20	10	
U148	74F543	12	24	6	
U149	74F543	12	24	6	

FIGURE 4-2. MYME224 SCHEMATIC DIAGRAM (SHEET 1 OF 25)

63DW3500B0C REV E SH 1 OF 25





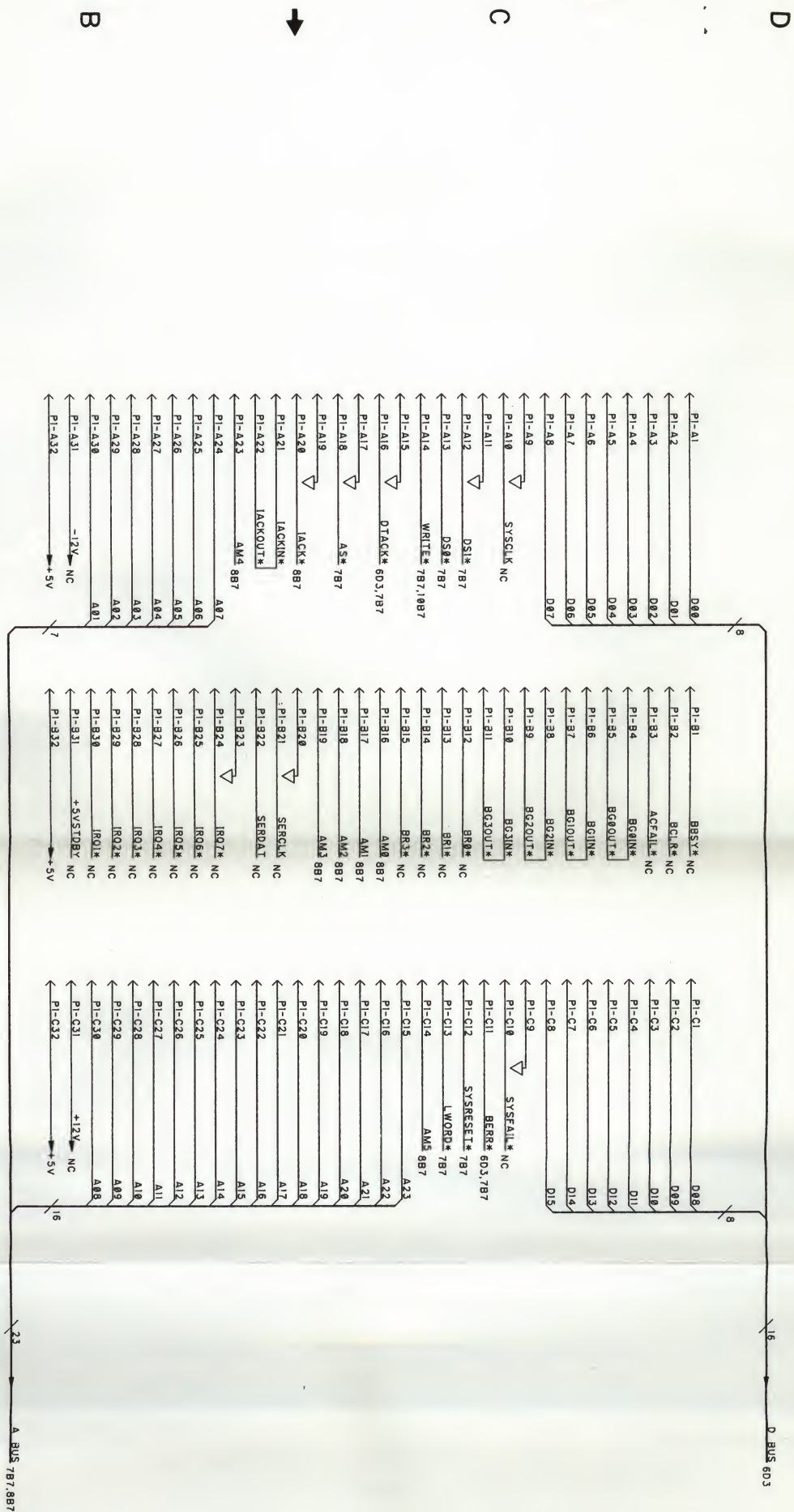
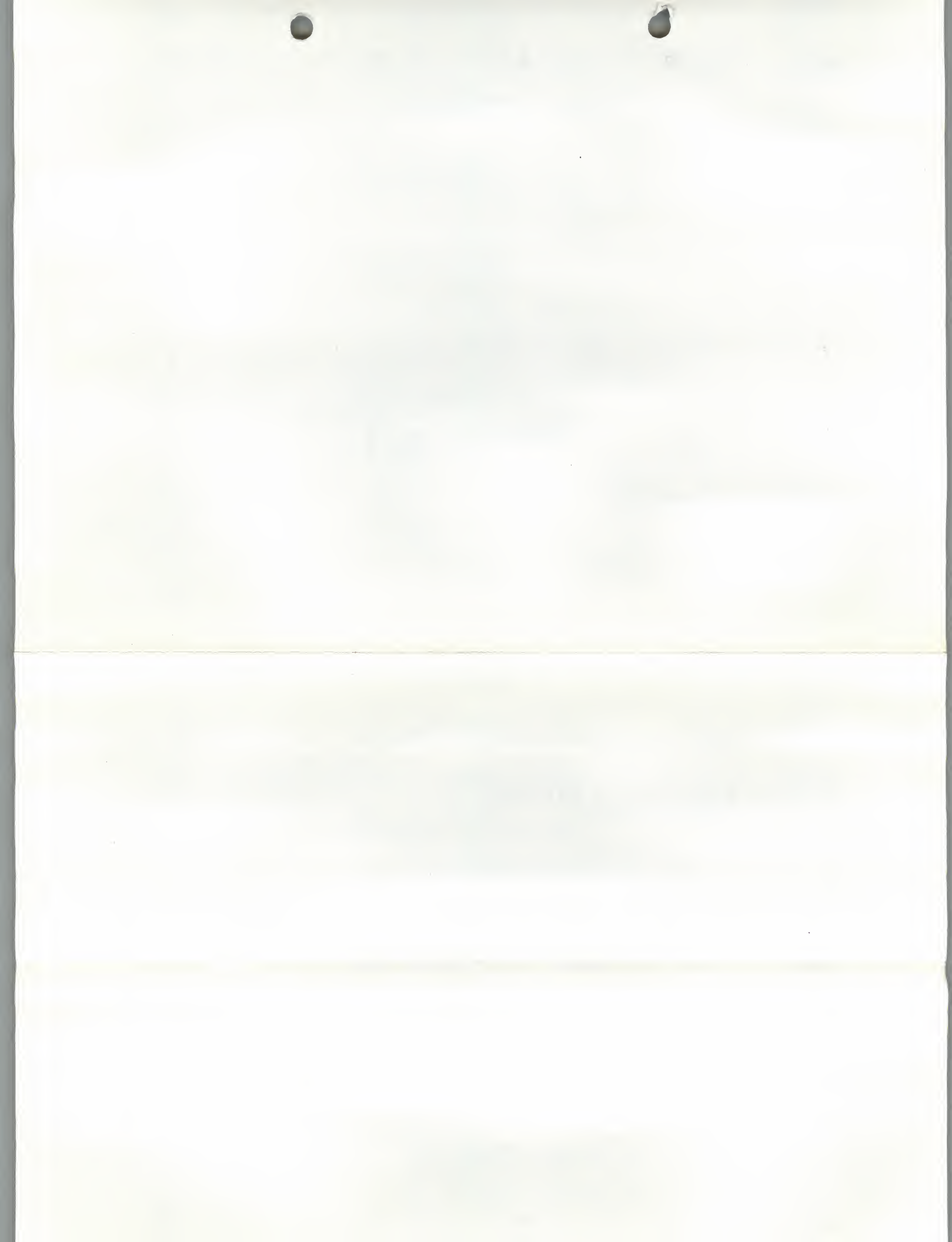


FIGURE 4-2. MNE224 SCHEMATIC DIAGRAM (SHEET 3 OF 25)



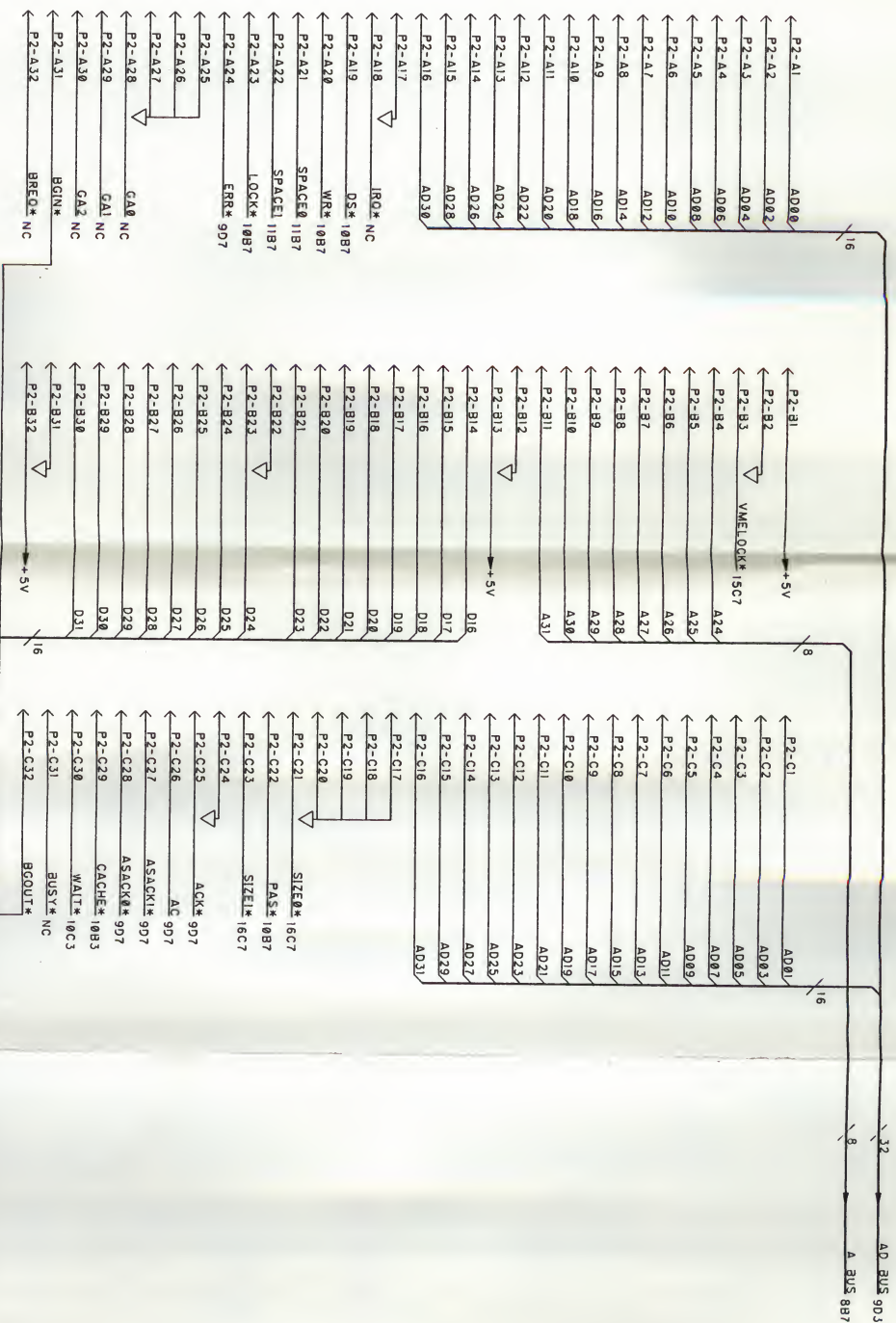


FIGURE 4-2. MVNE224 SCHEMATIC DIAGRAM (SHEET 4 OF 25)



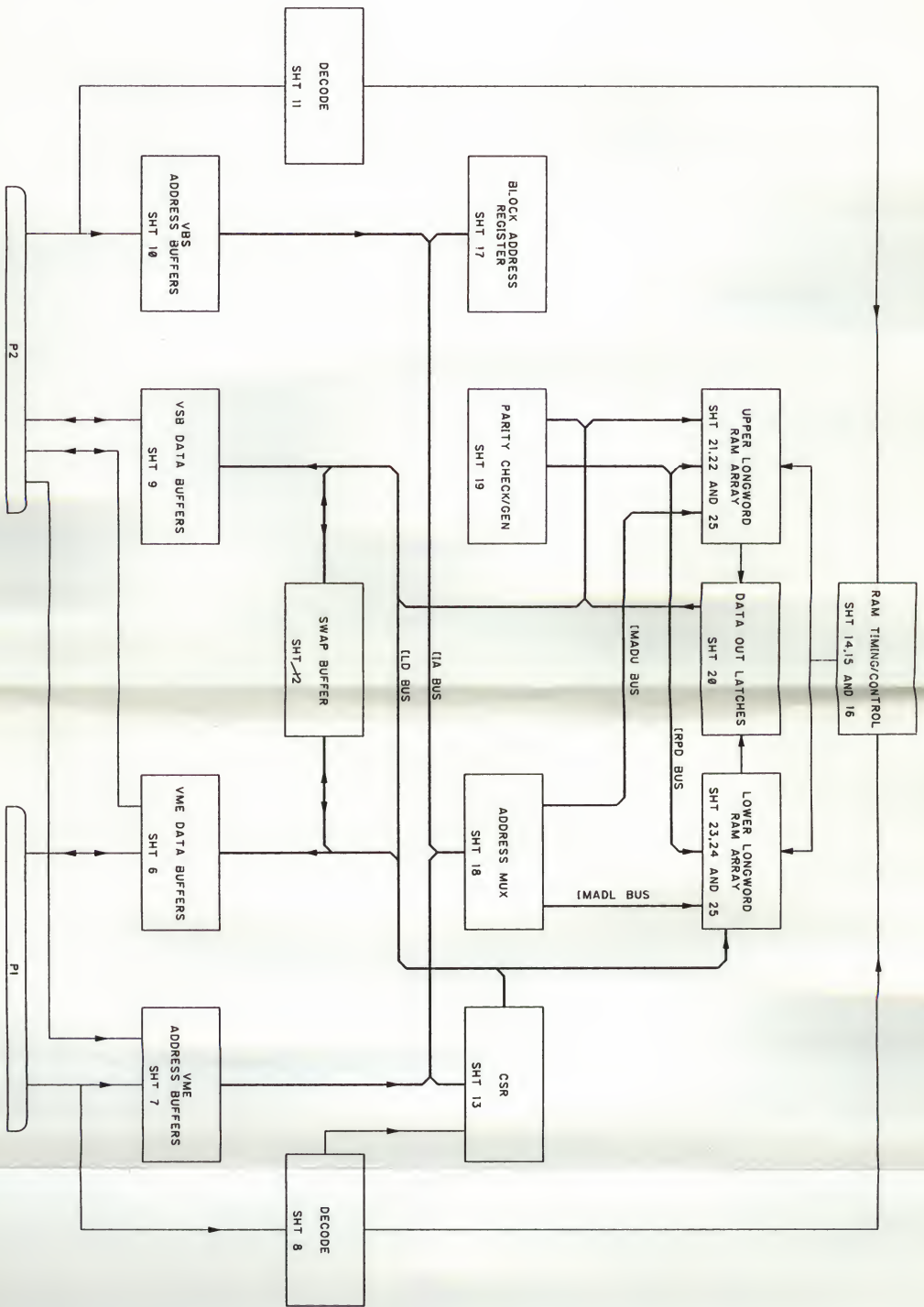
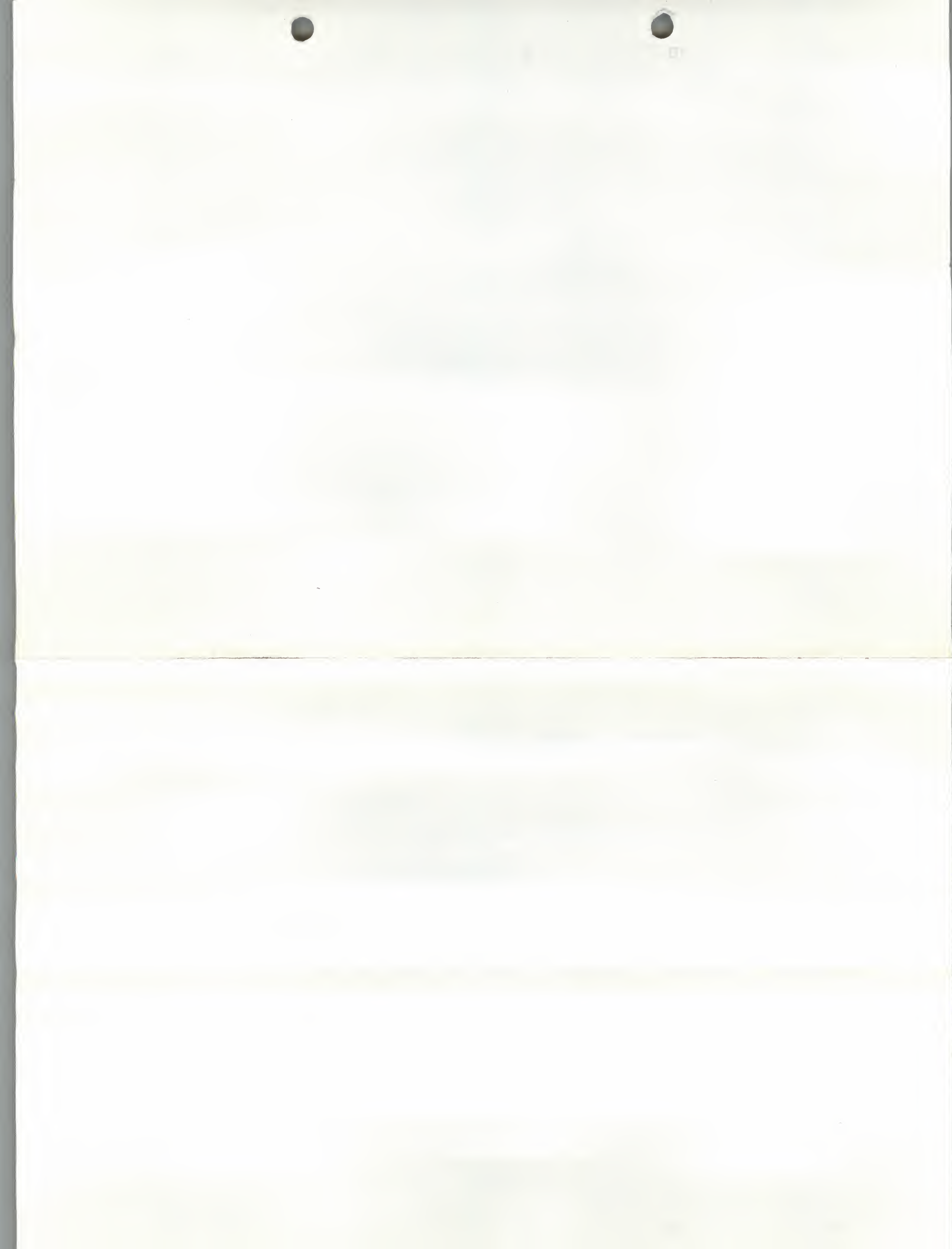
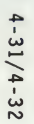
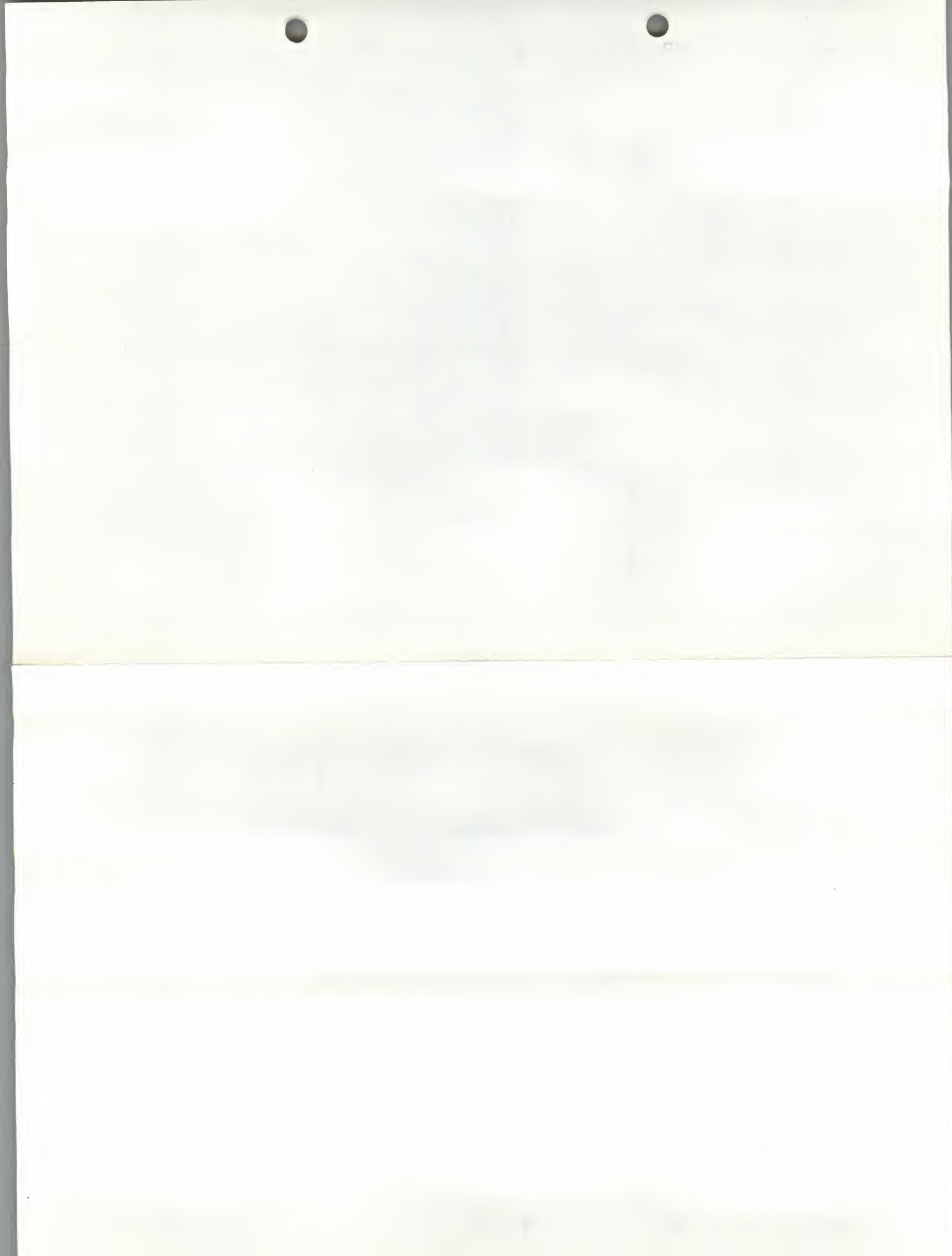


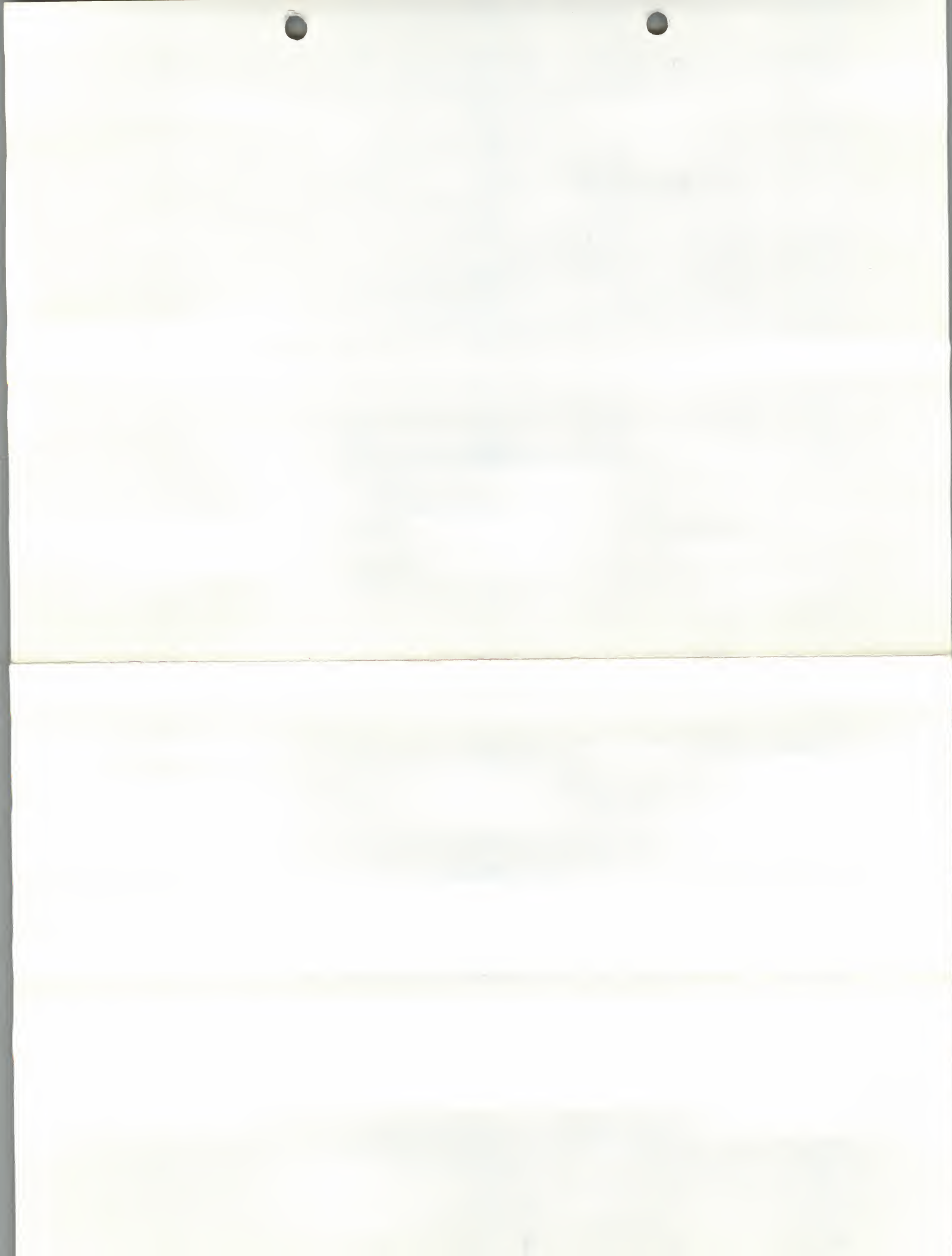
FIGURE 4-2. MVNE224 SCHEMATIC DIAGRAM (SHEET 5 OF 25)

BLOCK DIAGRAM
63DW3500B0C REV E SH 5 OF 25









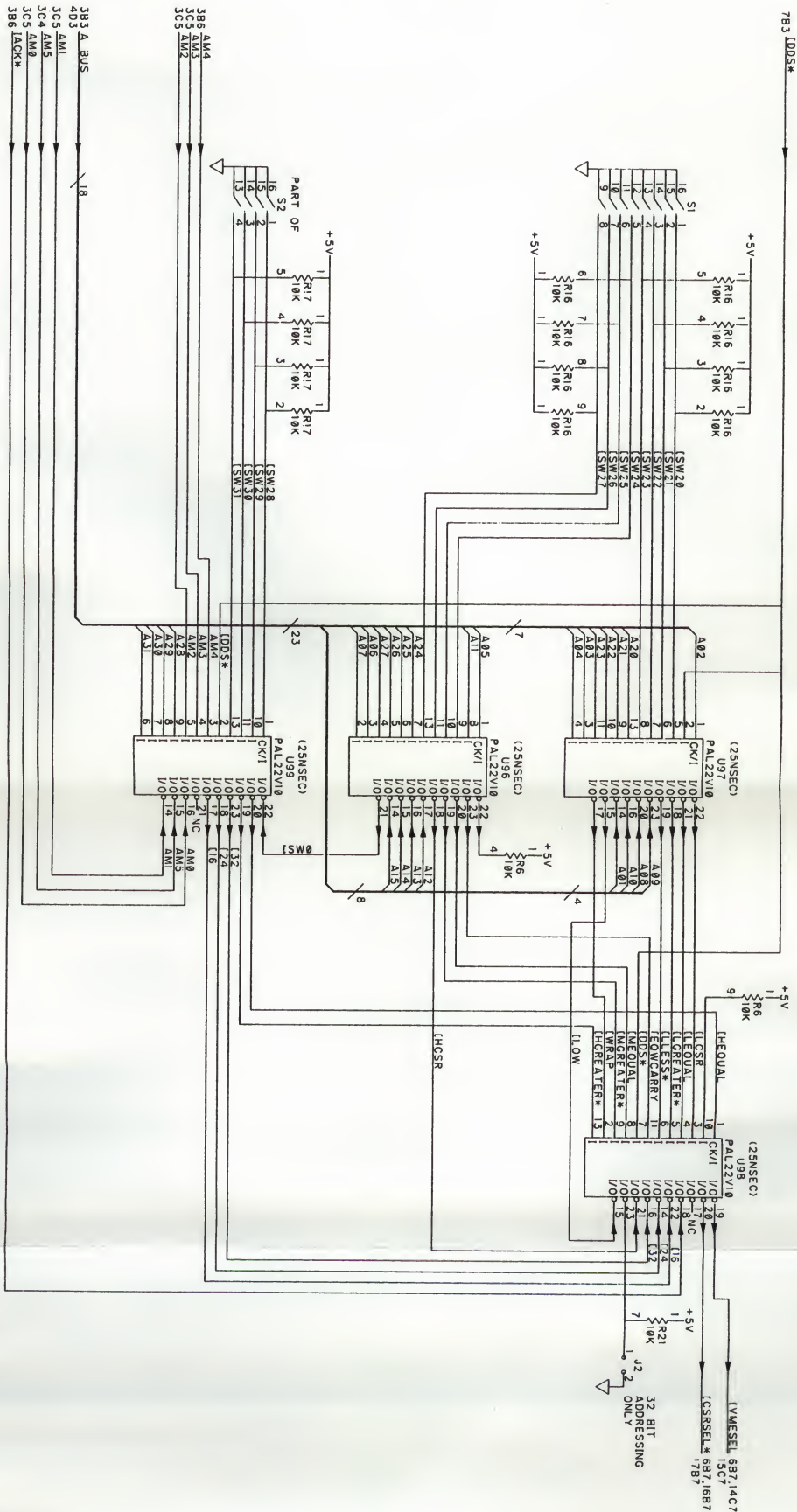
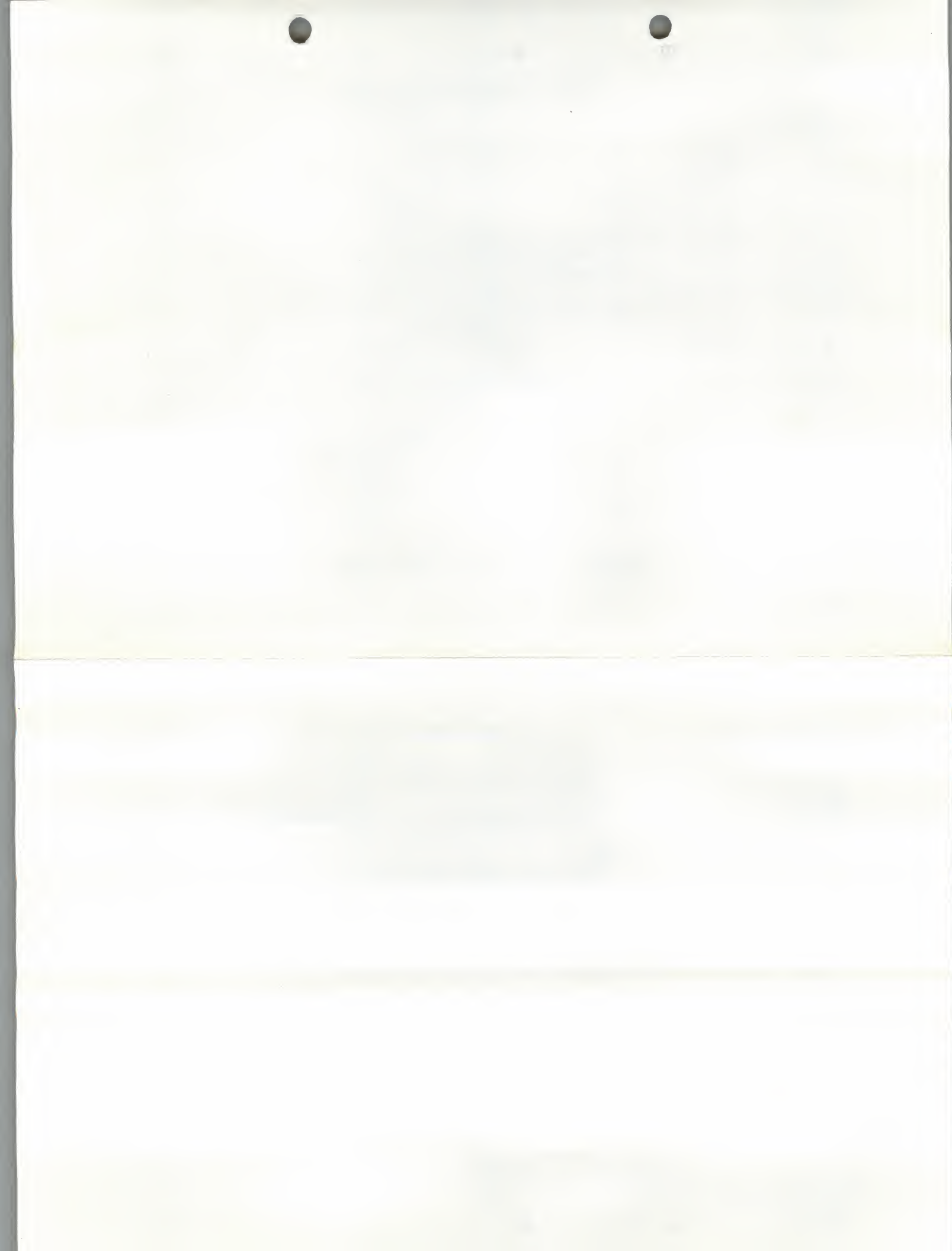


FIGURE 4-2. VME224 SCHEMATIC DIAGRAM (SHEET 8 OF 25)



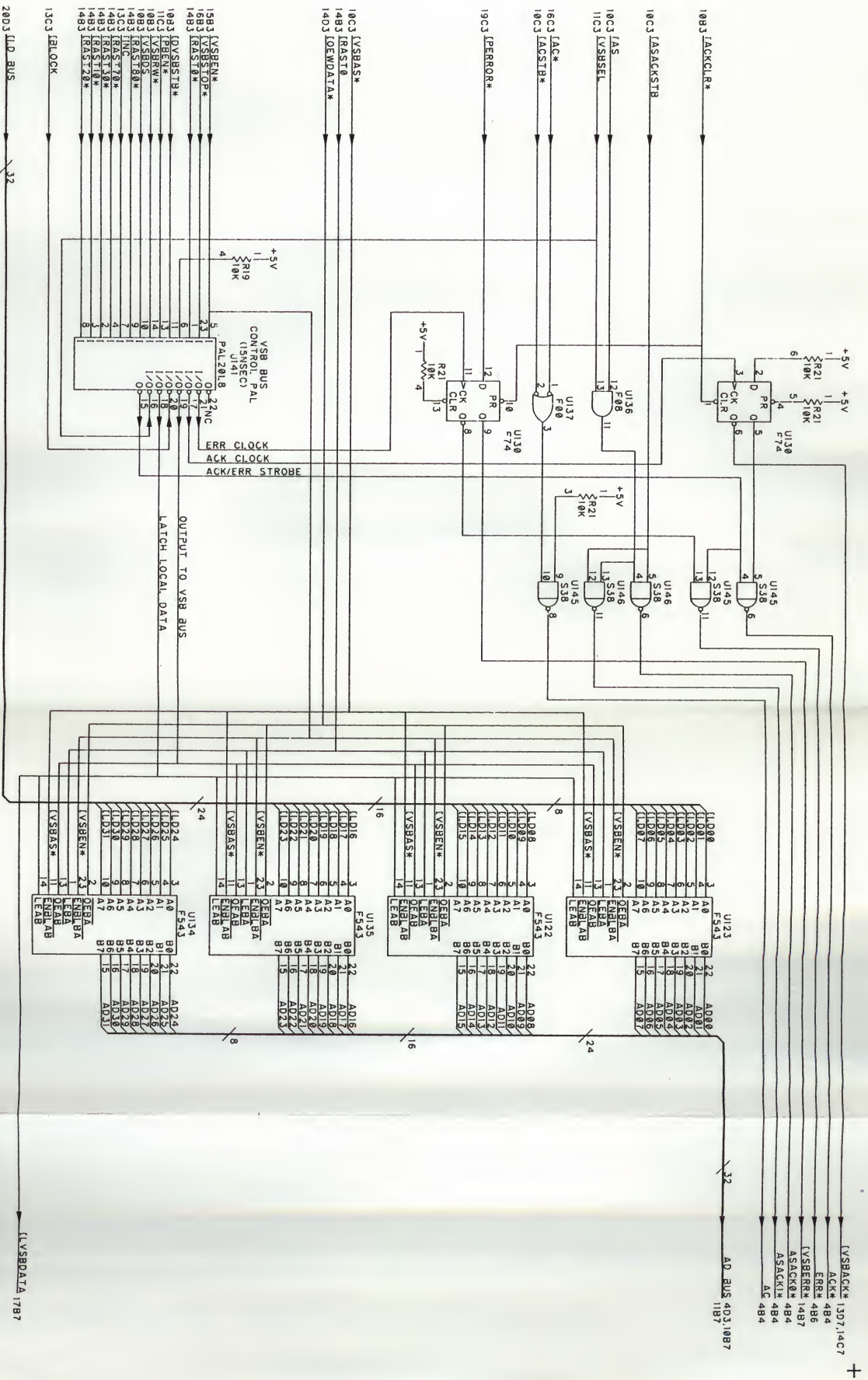
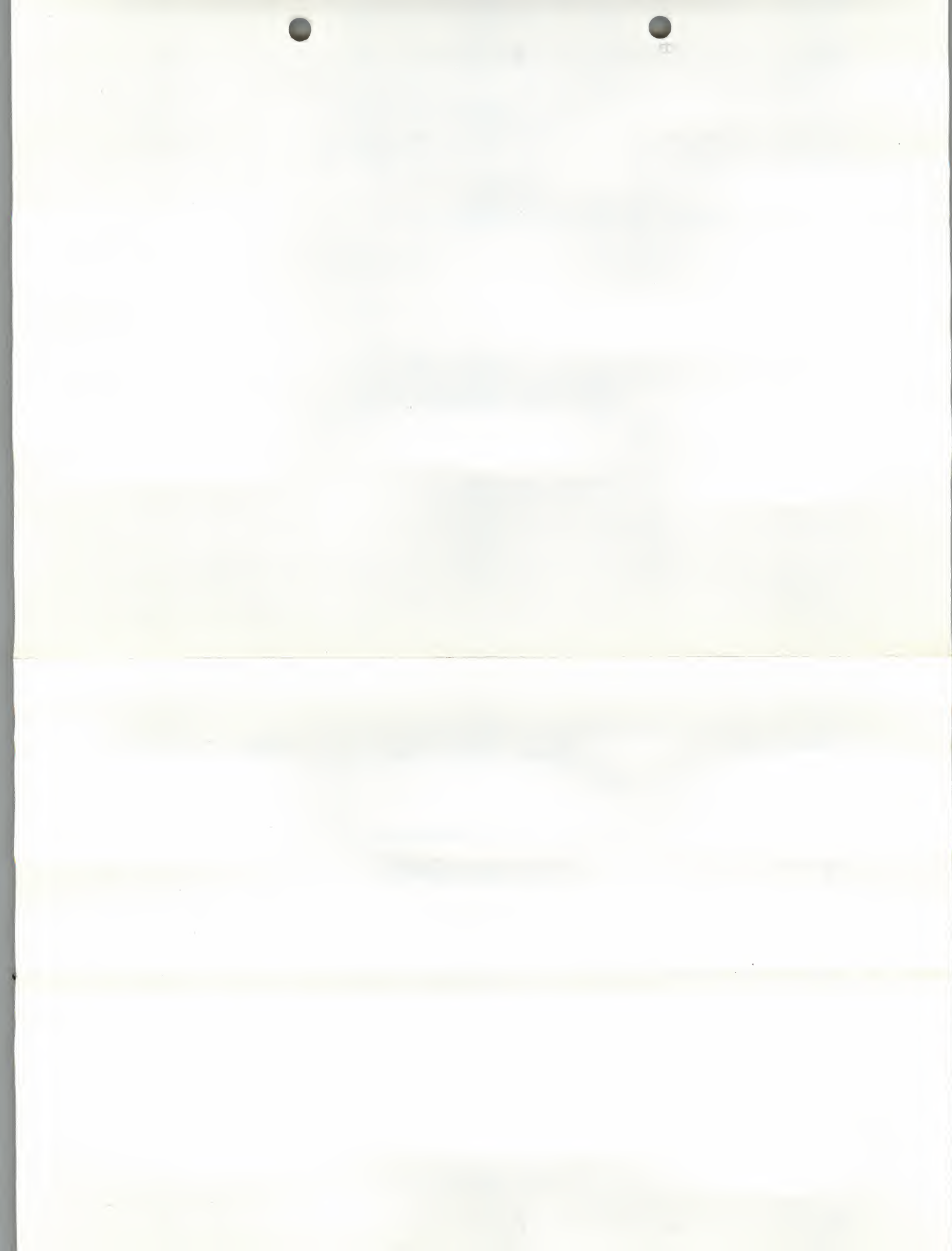


FIGURE 4-2. NMME224 SCHEMATIC DIAGRAM (SHEET 9 OF 25)



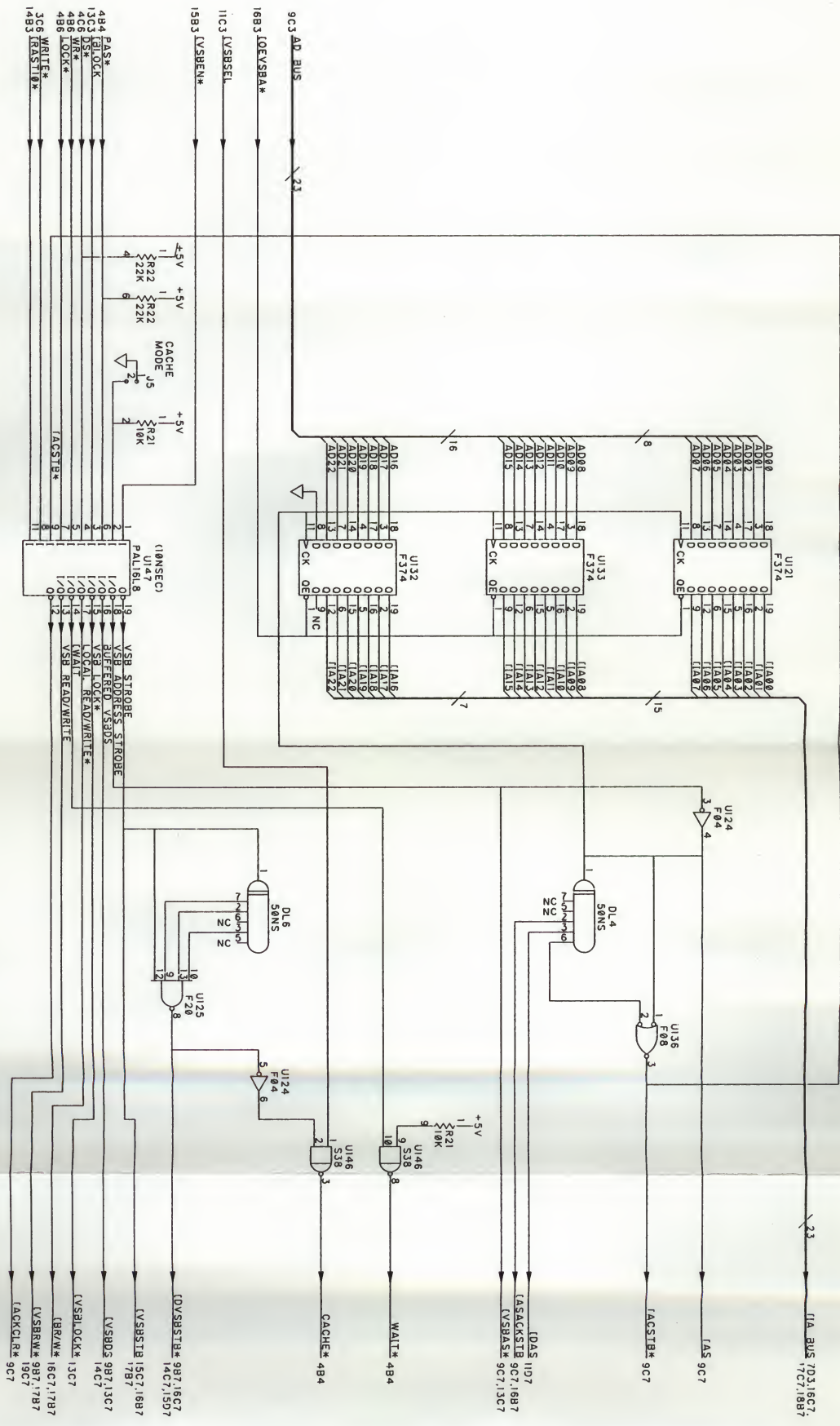
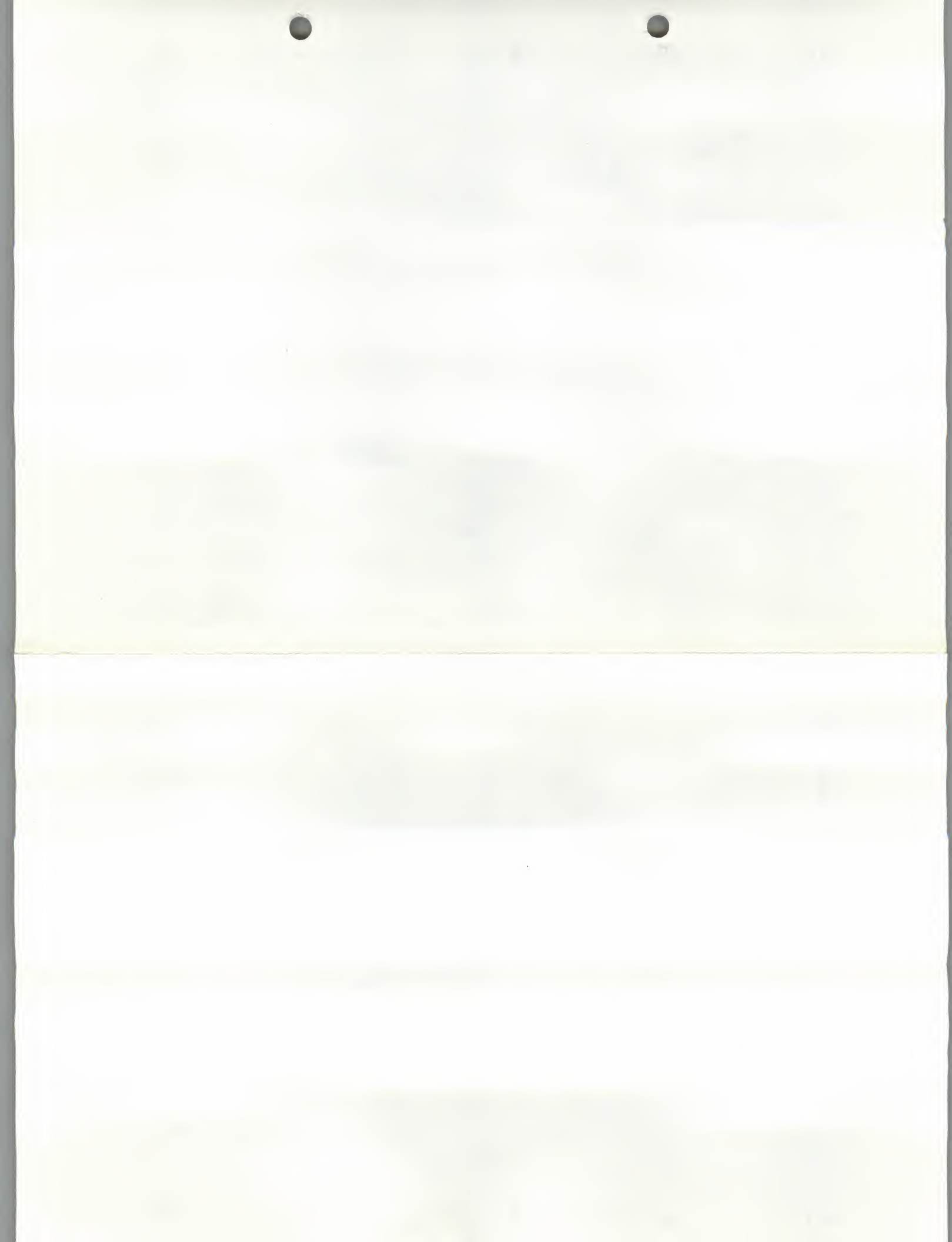
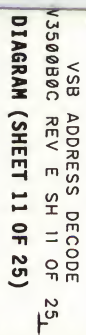


FIGURE 4-2. WME224 SCHEMATIC DIAGRAM (SHEET 10 OF 25)







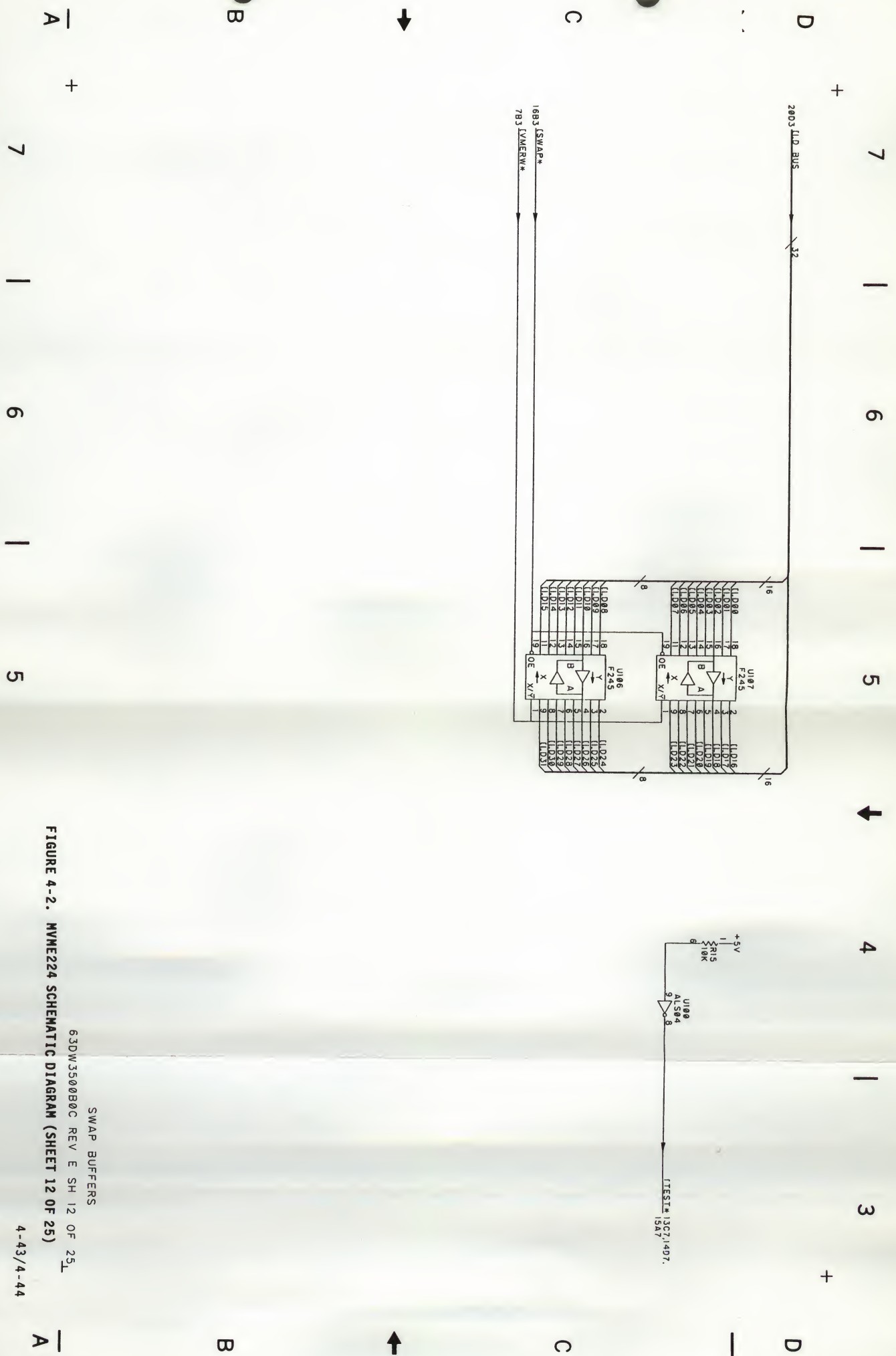
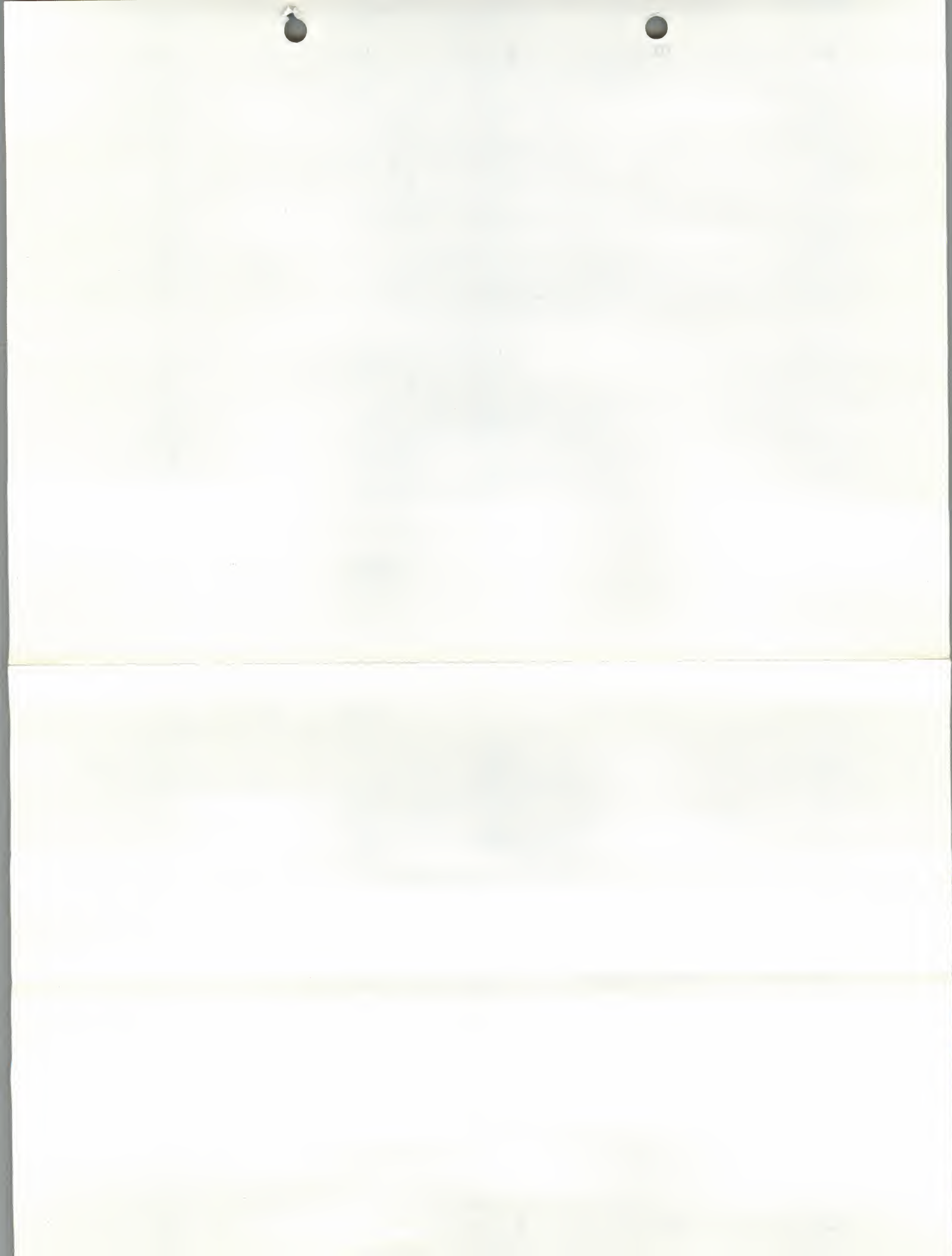
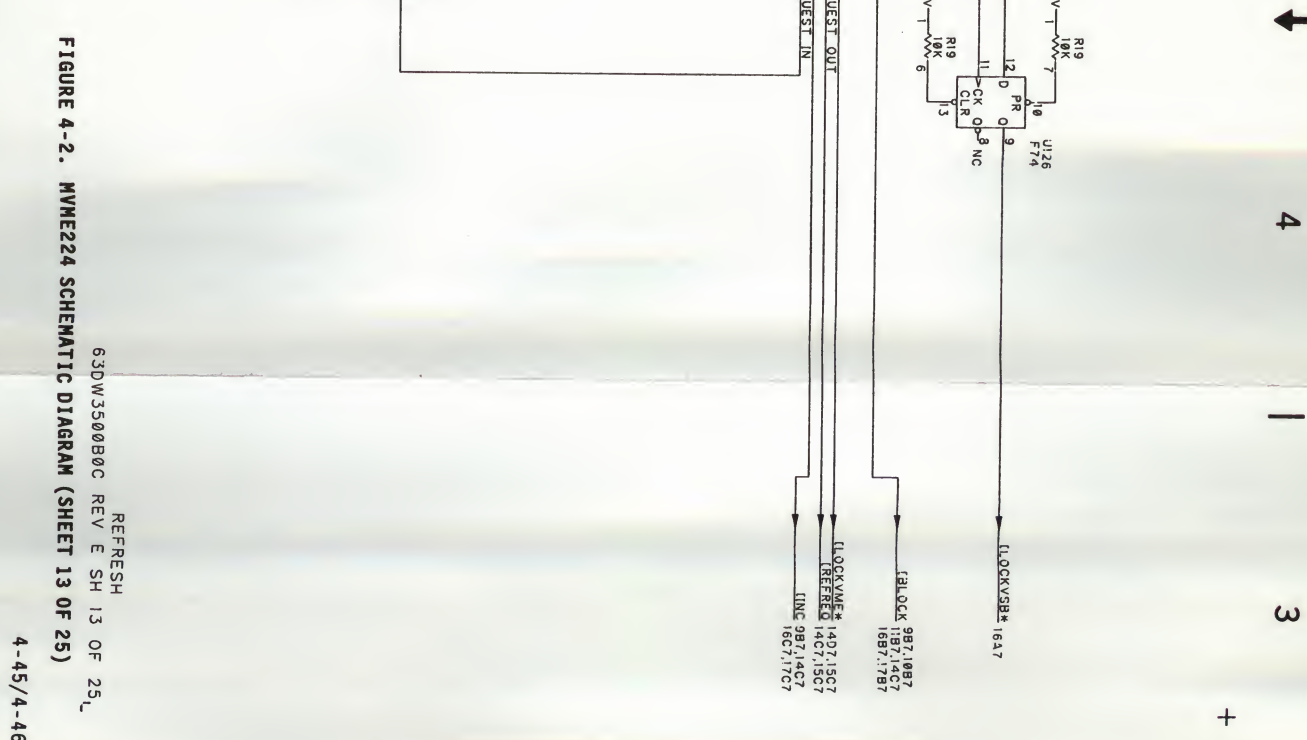
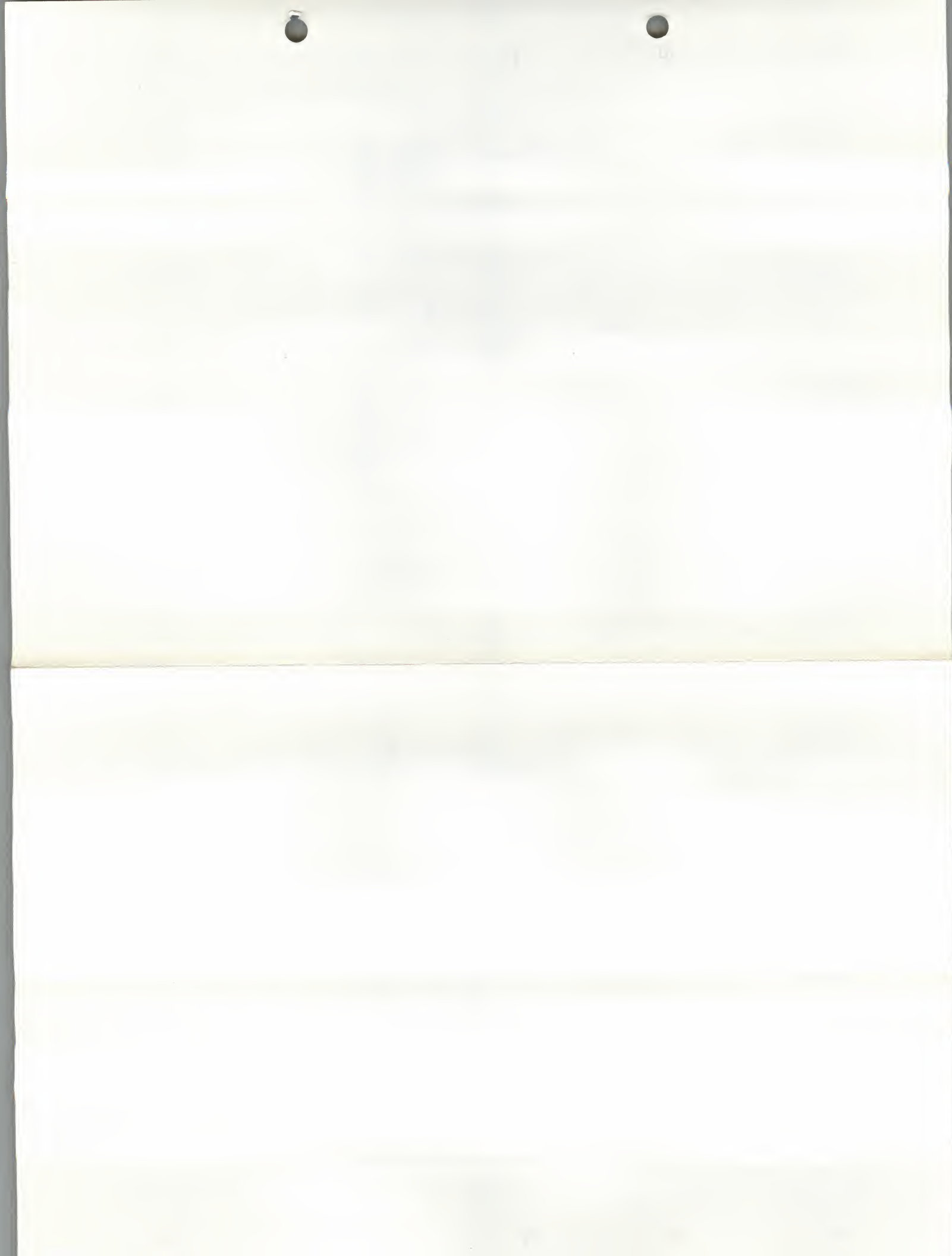


FIGURE 4-2. NVME224 SCHEMATIC DIAGRAM (SHEET 12 OF 25)





4-45/4-46



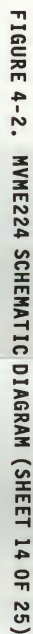
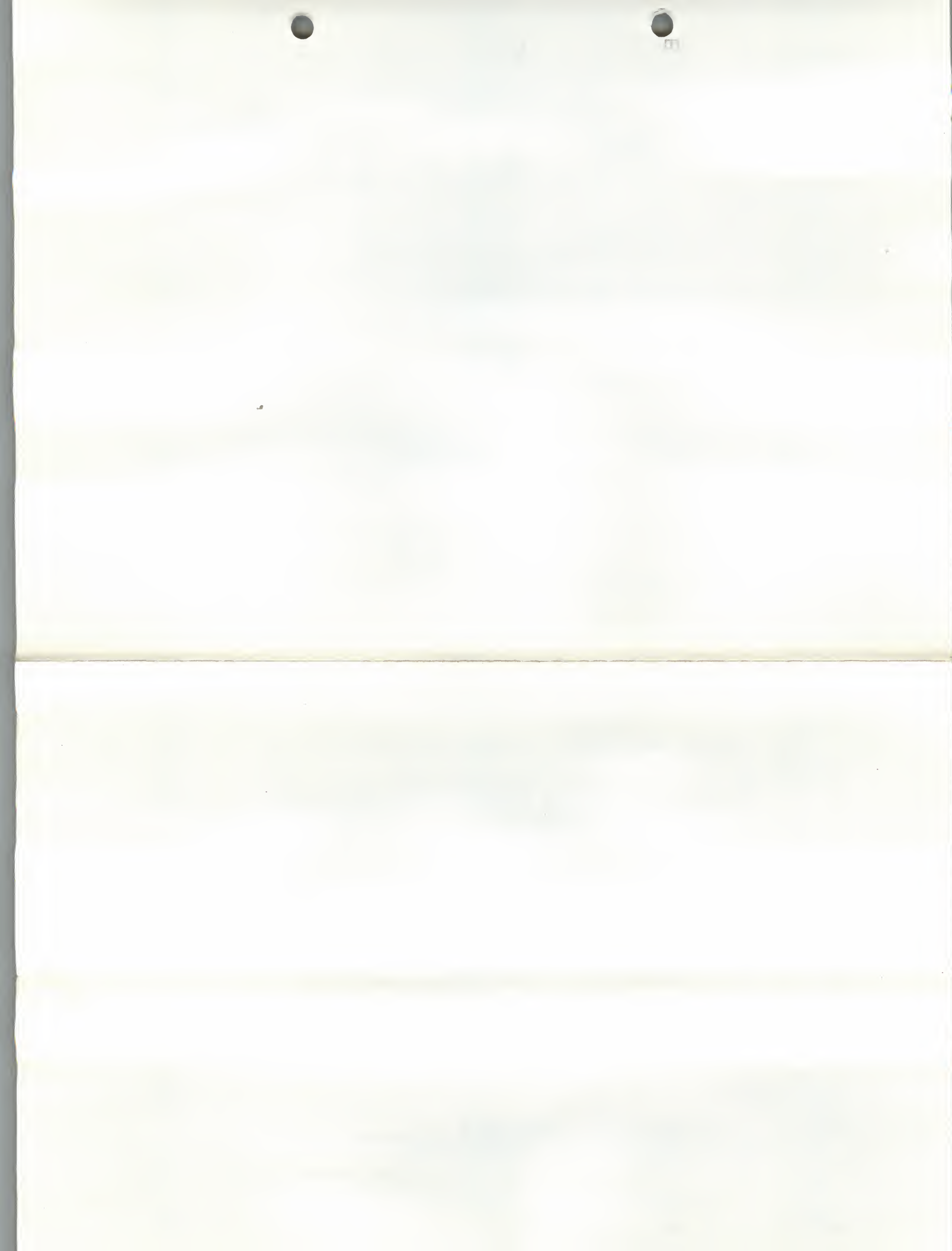


FIGURE 4-2. MVM224 SCHEMATIC DIAGRAM (SHEET 14 OF 25)



A

14B3 TRASTIA*
12C3 TEST*

7

CYCLE ARBITRATION
350B0C REV E SH 15 OF 25
DIAGRAM (SHEET 15 OF 25)

4-49/4-50

A

B

14B3 IT0*

ENABLE*
[VSBEN* 9B7,10B7
[REFEN* 14C7,16B7
[RVMEEN* 16B7,19C7
[VSBEN* 16B7,19C7
[REFEN* 16B7
[RVMEEN* 6B7,13C7
17B

B

→

C

10B3 VSBST*
13C3 LOCKVME*
14B3 CLREF*

[RVSELCK 14C7

C

D

7B3 [VMEDS]
10B3 [VSBST1B*

[VMEDS 14C7,16B7

D

+

7

|

|

3

+

-



A

B

C

D

7 1 3 +

A

B

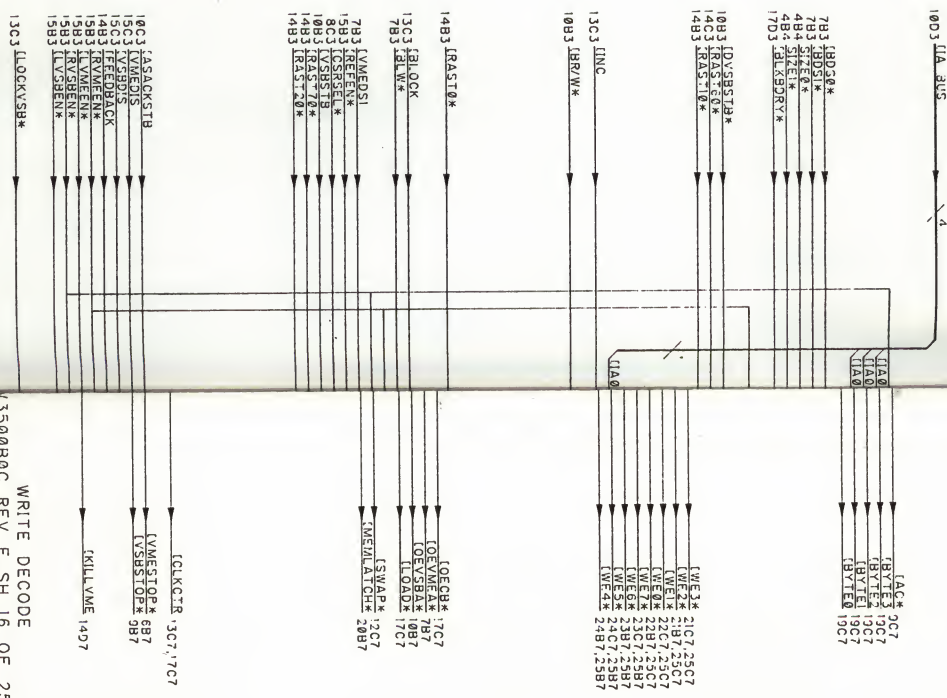
C

D

7

WRITE DECODE
J3500B0C REV E SH 16 OF 25
DIAGRAM (SHEET 16 OF 25)

4-51/4-52





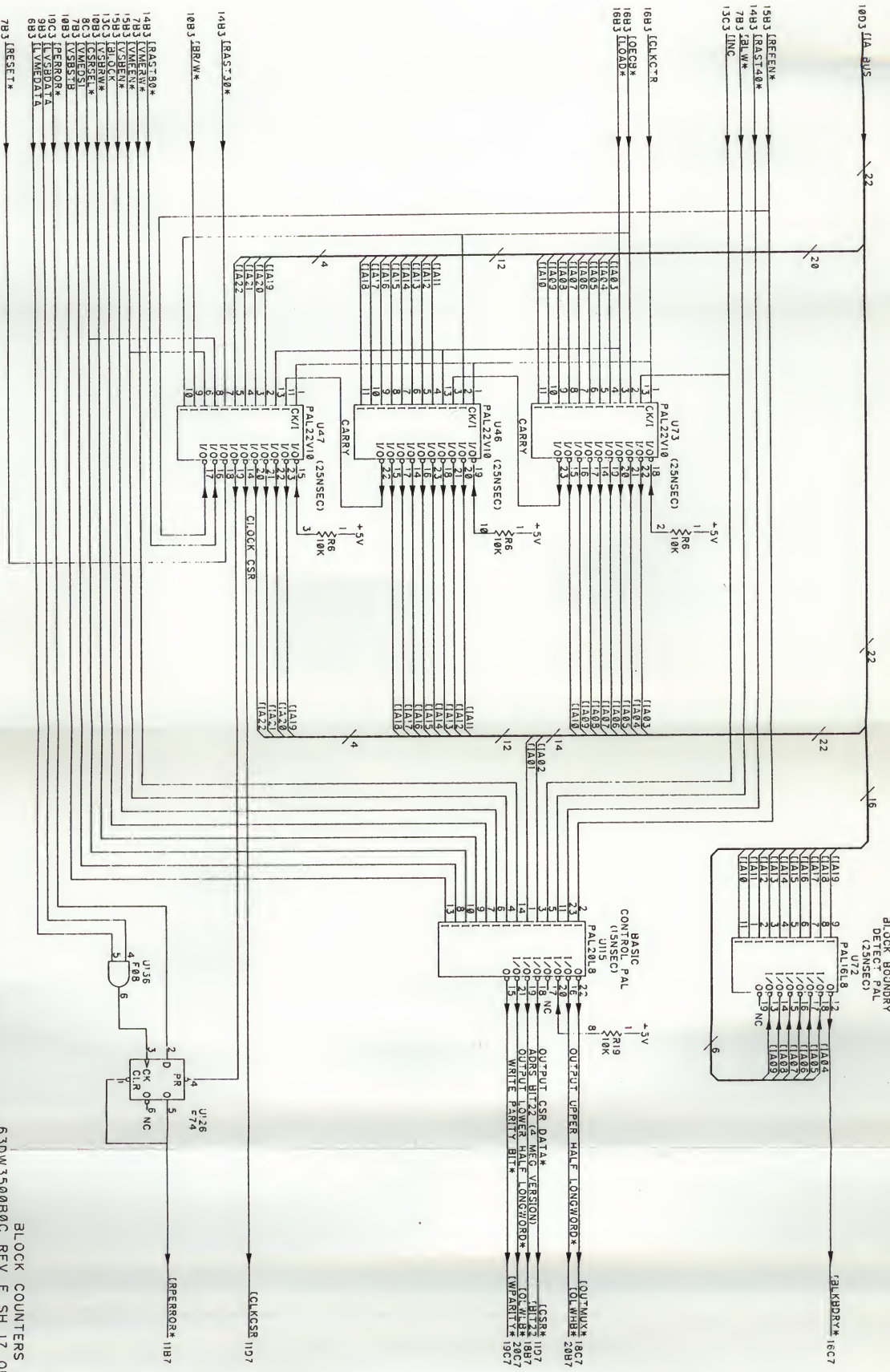
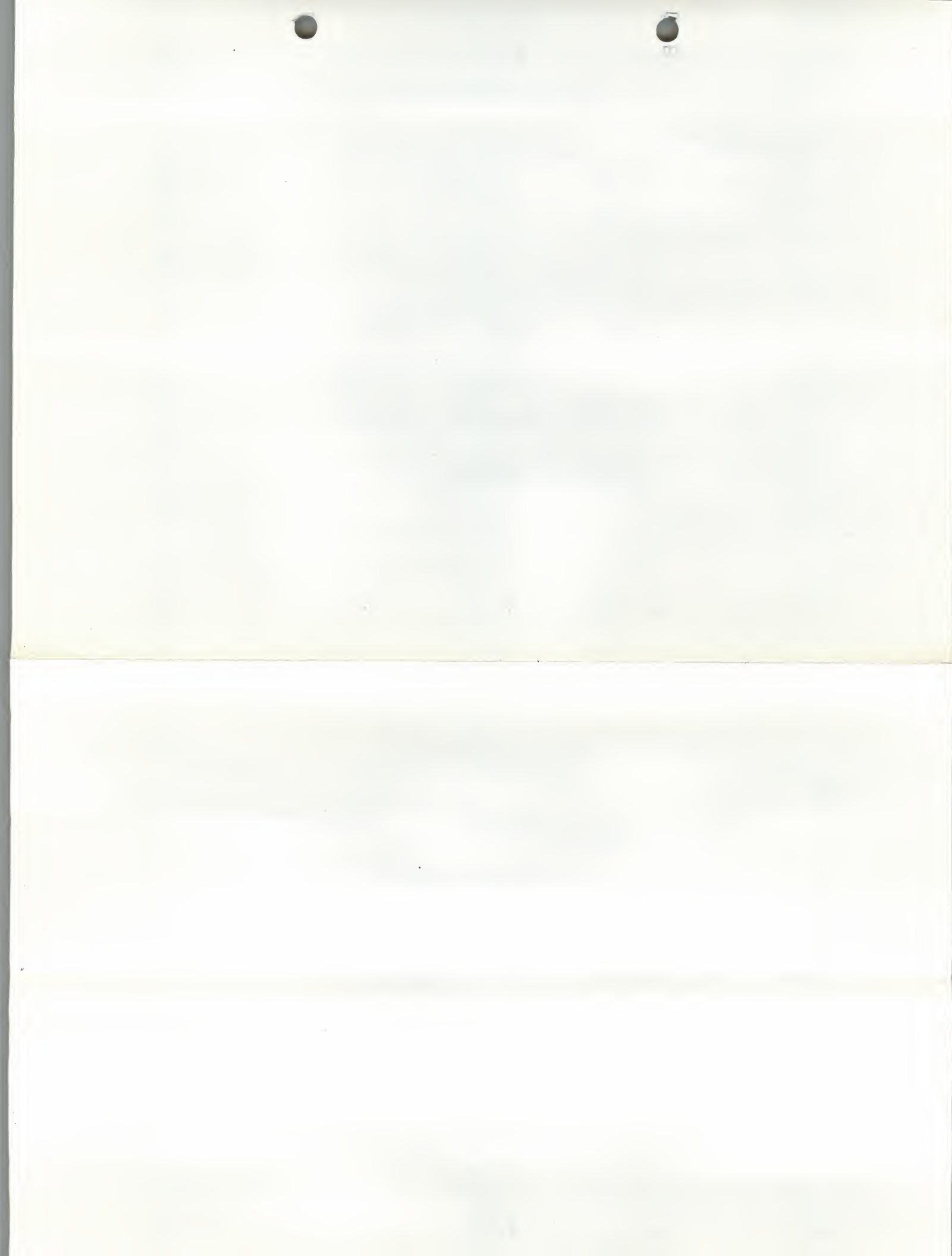


FIGURE 4-2. WVME224 SCHEMATIC DIAGRAM (SHEET 17 OF 25)



D

+

7

|

|

3

+

D

14B3 [RAS*20*]

10 [MADL BUS 21C7 22C7 25C7]

17C3 [OUTMUX*]

C

C

→

↑

B

17C3 [MT22]

4 MEG4

10D3 [ILA BUS] 20

8 MEG4

A

+

7

|

ADDRESS MULTIPLEXERS
W3500B0C REV E SH 18 OF 25_L
DIAGRAM (SHEET 18 OF 25)

4-55/4-56

A

10 [MADU BUS 23C7 24C7 25B7]





A + D C B

7 + 7

1 1

3 +

10 16 26 32

17C3 LQ.W.H.B* 2393 LQ.DP.DUS 21C3 LQ.DUS 10B3 LQ.MEM.LATCH*

18D0 18D1 18D2 18D3 18D4 18D5 18D6 18D7 18D8 18D9 18DA 18DB 18DC 18DD 18DE 18DF 18D0 18D1 18D2 18D3 18D4 18D5 18D6 18D7 18D8 18D9 18DA 18DB 18DC 18DD 18DE 18DF

687.287 11D.DUS 11D3.12D7 1987.21D7 22D7.23D7 11DP.DUS 1287

10 16 26 32

17C3 LQ.W.H.B* 2393 LQ.DP.DUS 21C3 LQ.DUS 10B3 LQ.MEM.LATCH*

18D0 18D1 18D2 18D3 18D4 18D5 18D6 18D7 18D8 18D9 18DA 18DB 18DC 18DD 18DE 18DF

687.287 11D.DUS 11D3.12D7 1987.21D7 22D7.23D7 11DP.DUS 1287

10 16 26 32

17C3 LQ.W.H.B* 2393 LQ.DP.DUS 21C3 LQ.DUS 10B3 LQ.MEM.LATCH*

18D0 18D1 18D2 18D3 18D4 18D5 18D6 18D7 18D8 18D9 18DA 18DB 18DC 18DD 18DE 18DF

687.287 11D.DUS 11D3.12D7 1987.21D7 22D7.23D7 11DP.DUS 1287

10 16 26 32

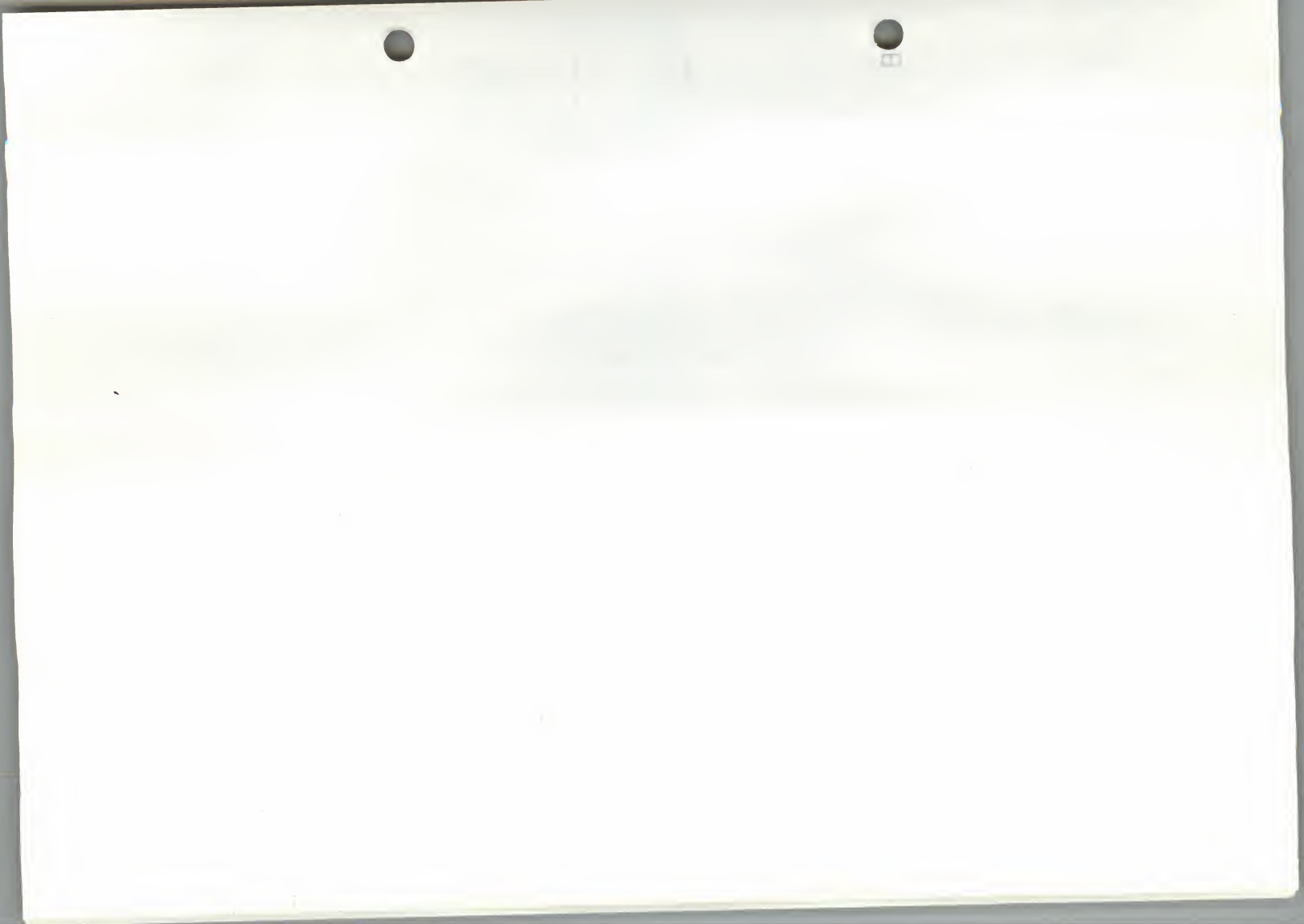
17C3 LQ.W.H.B* 2393 LQ.DP.DUS 21C3 LQ.DUS 10B3 LQ.MEM.LATCH*

18D0 18D1 18D2 18D3 18D4 18D5 18D6 18D7 18D8 18D9 18DA 18DB 18DC 18DD 18DE 18DF

687.287 11D.DUS 11D3.12D7 1987.21D7 22D7.23D7 11DP.DUS 1287

MEMORY OUT DATA LATCHES
3500B0C REV E SH 20 OF 25
DIAGRAM (SHEET 20 OF 25)

4-59/4-60



7

3

+

+

D

D

2803 LLD BUS

1803 MADL BUS

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

RD BUS 2087/22C3
23C3/24C3

+

+

16

7

8

16

7

8

16

7

8

16

7

8

U8
MSM4C1000L
U9
MSM4C1000L

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

B

B

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

16C3 WE2*
16C3 CAS*
16C3 RAS*
16C3 TEST

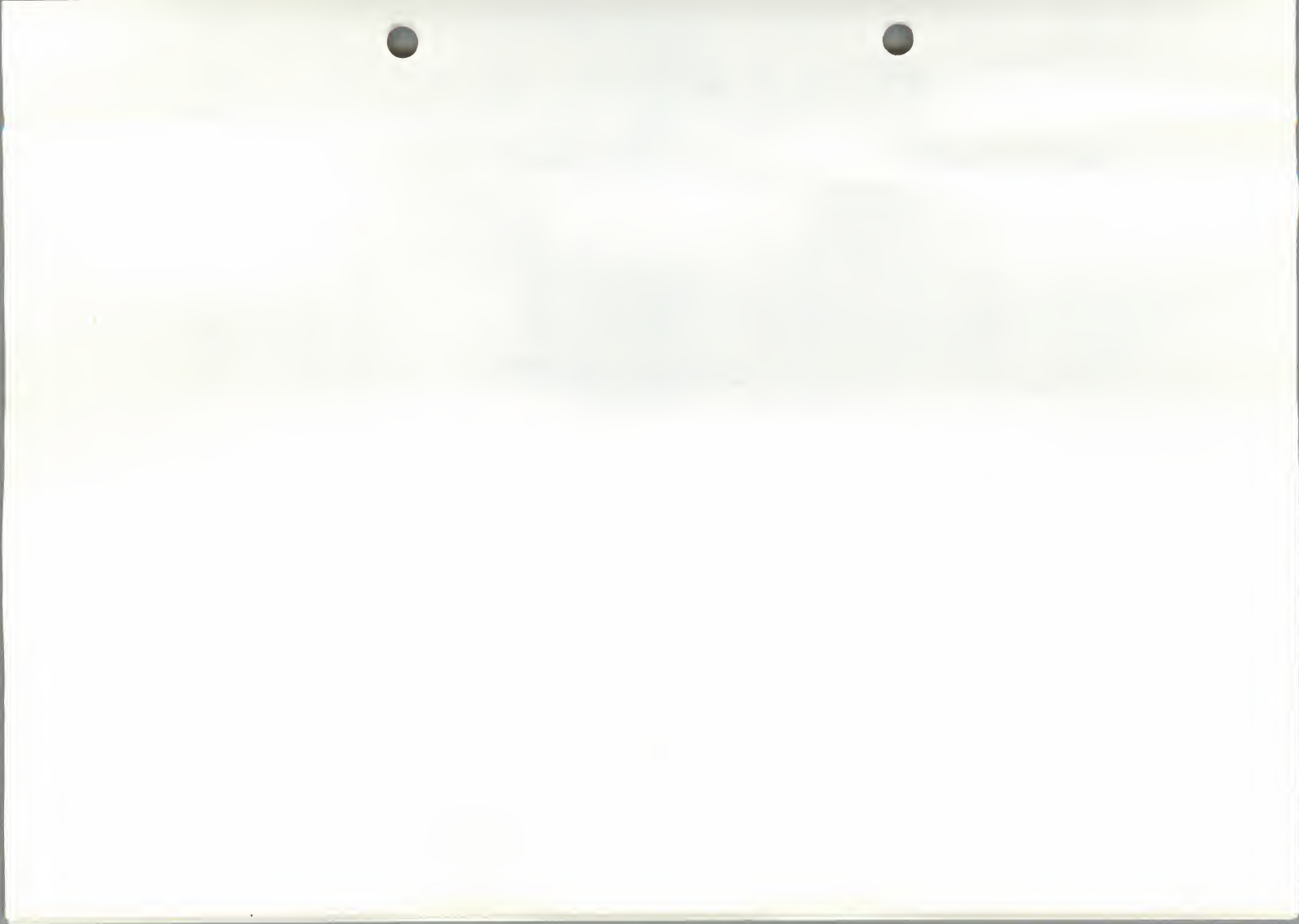
A

A

VME224 DRAM- LOWER
BYTES 2 AND 3
DW3500B0C REV E SH 21 OF 25L

IC DIAGRAM (SHEET 21 OF 25)

4-61/4-62



7 3

D

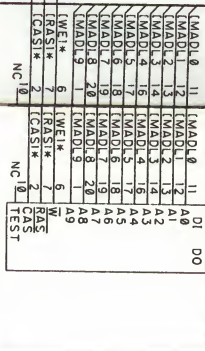
+

D

2003 LLD BUS

1803 LLD BUS

16C3 WEI*
14C3 RAS*
14C3 CAS*

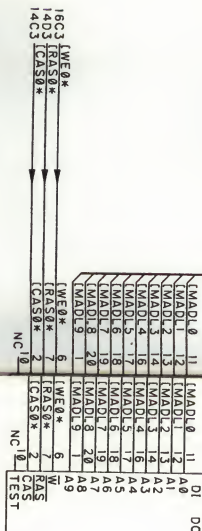


C

IRD BUS 21C3

ILD24
IRD24

U35 5M4C1000L
U36 5M4C1000L



B

A

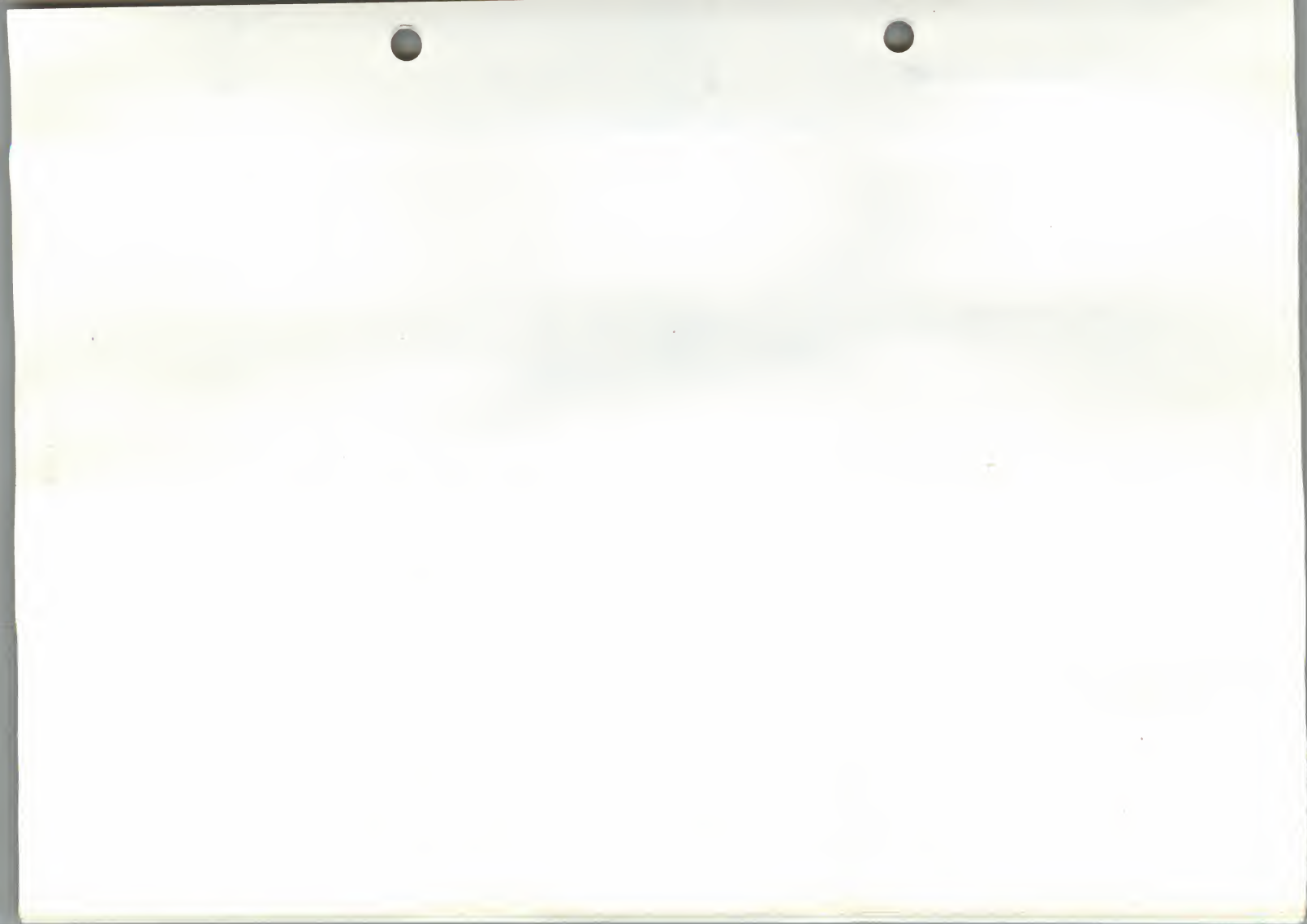
+

7

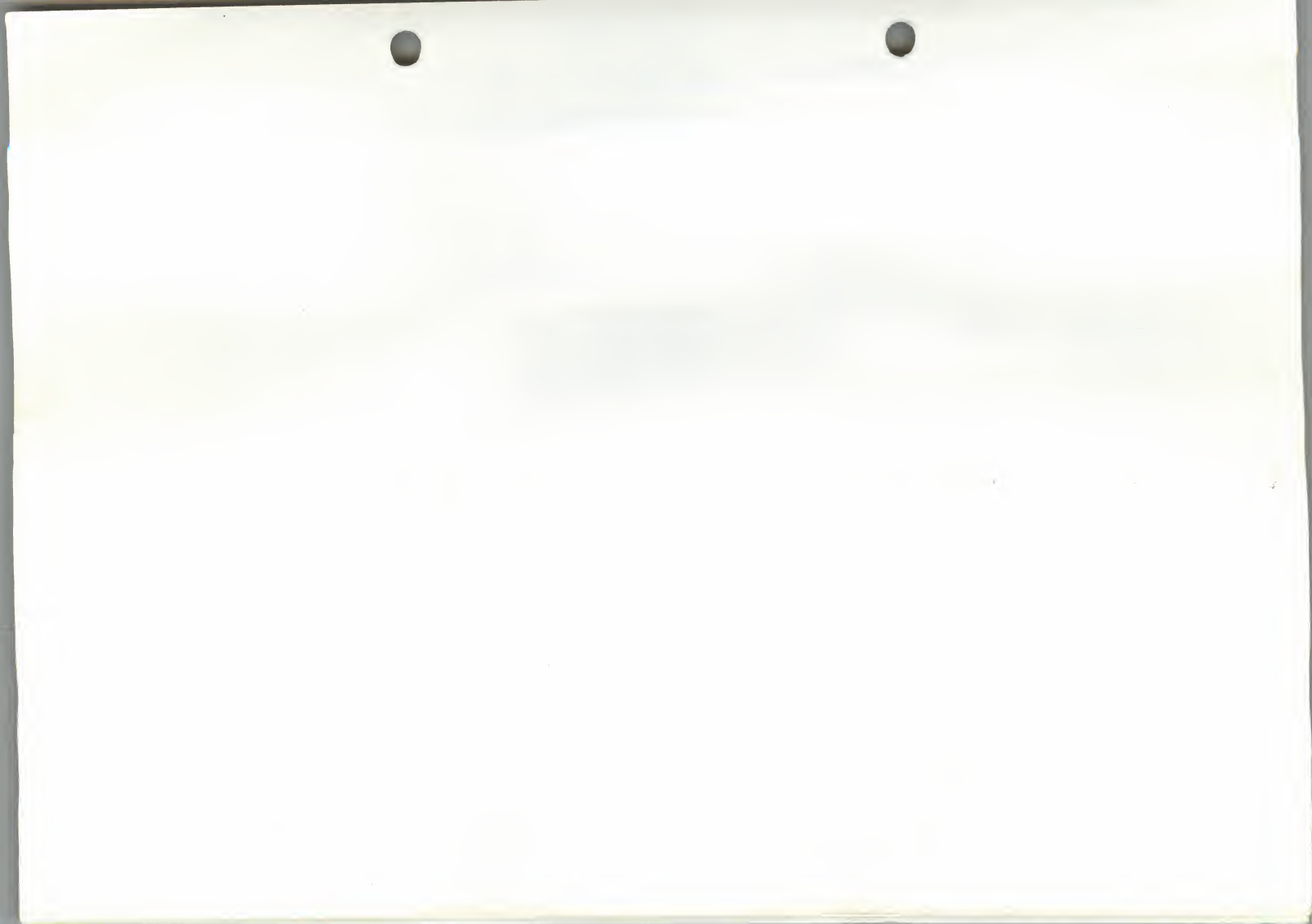
VME224 DRAM- LOWER
BYTES 0 AND 1 OF 25
W3500B0C REV E SH 22 OF 25
C DIAGRAM (SHEET 22 OF 25)

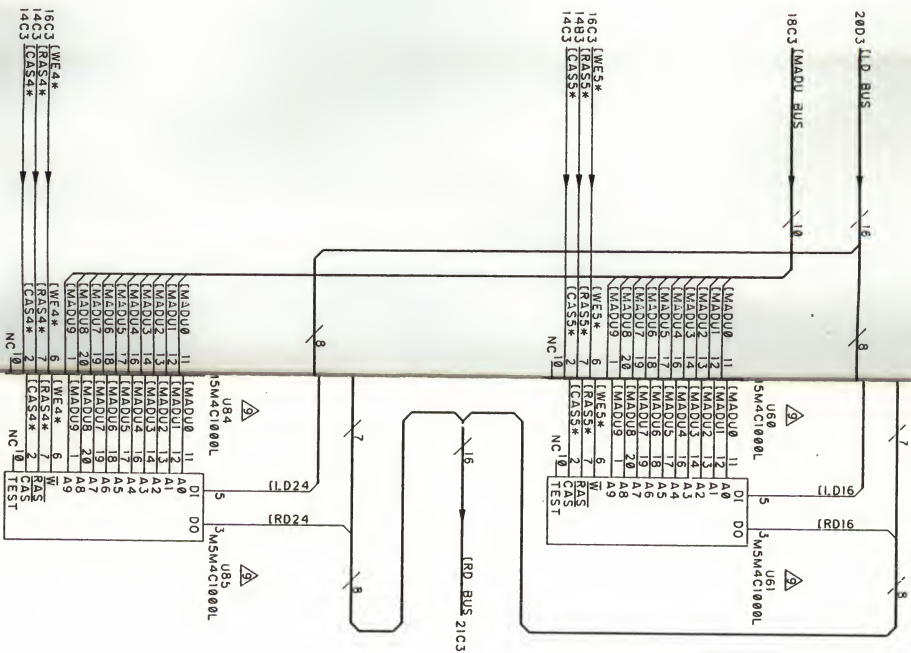
4-63/4-64

A





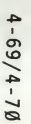


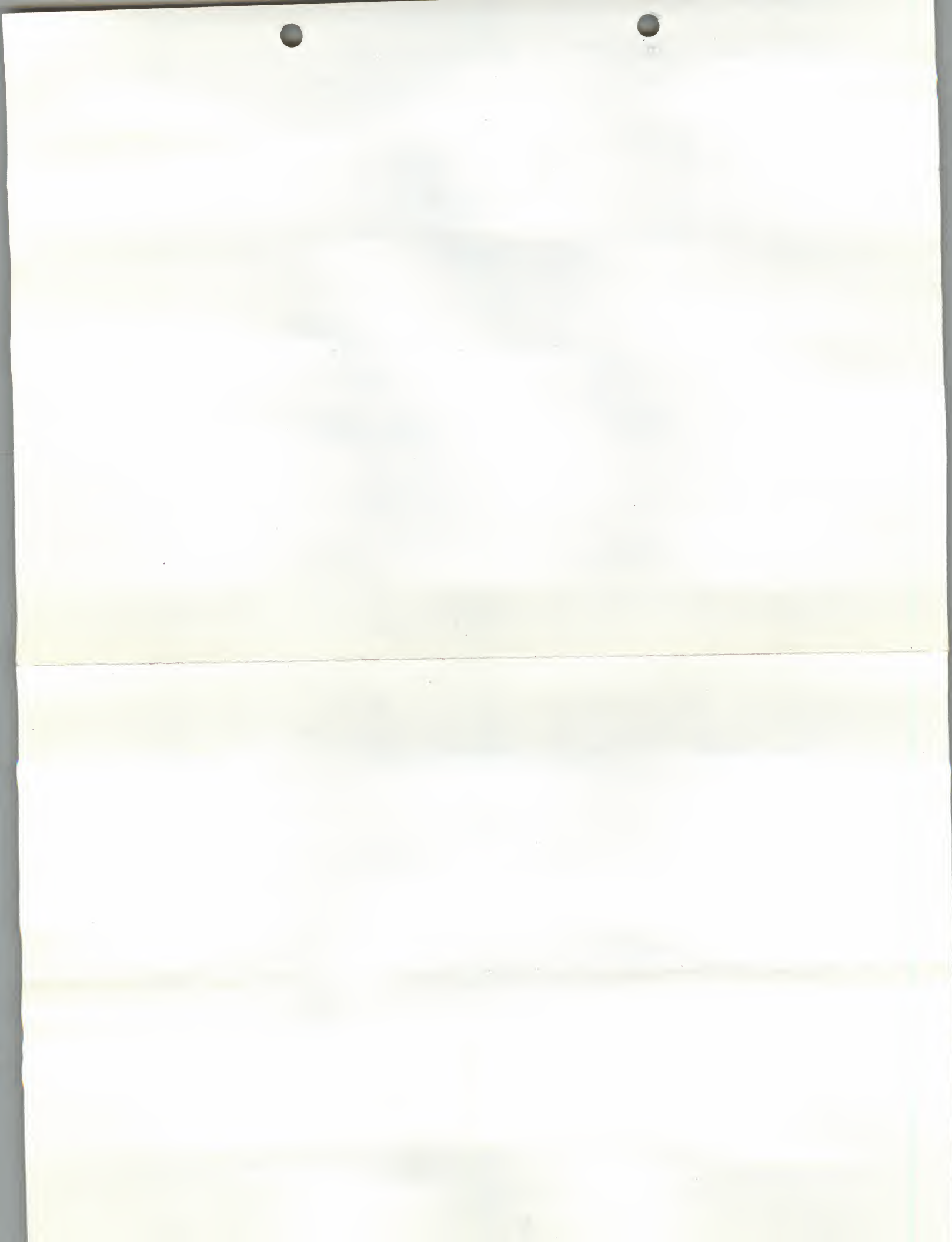


VME224 DRAM- UPPER
 BYTES 0 AND 1
 W350B0C REV E SH 24 OF 25
 C DIAGRAM (SHEET 24 OF 25)

4-67/4-68







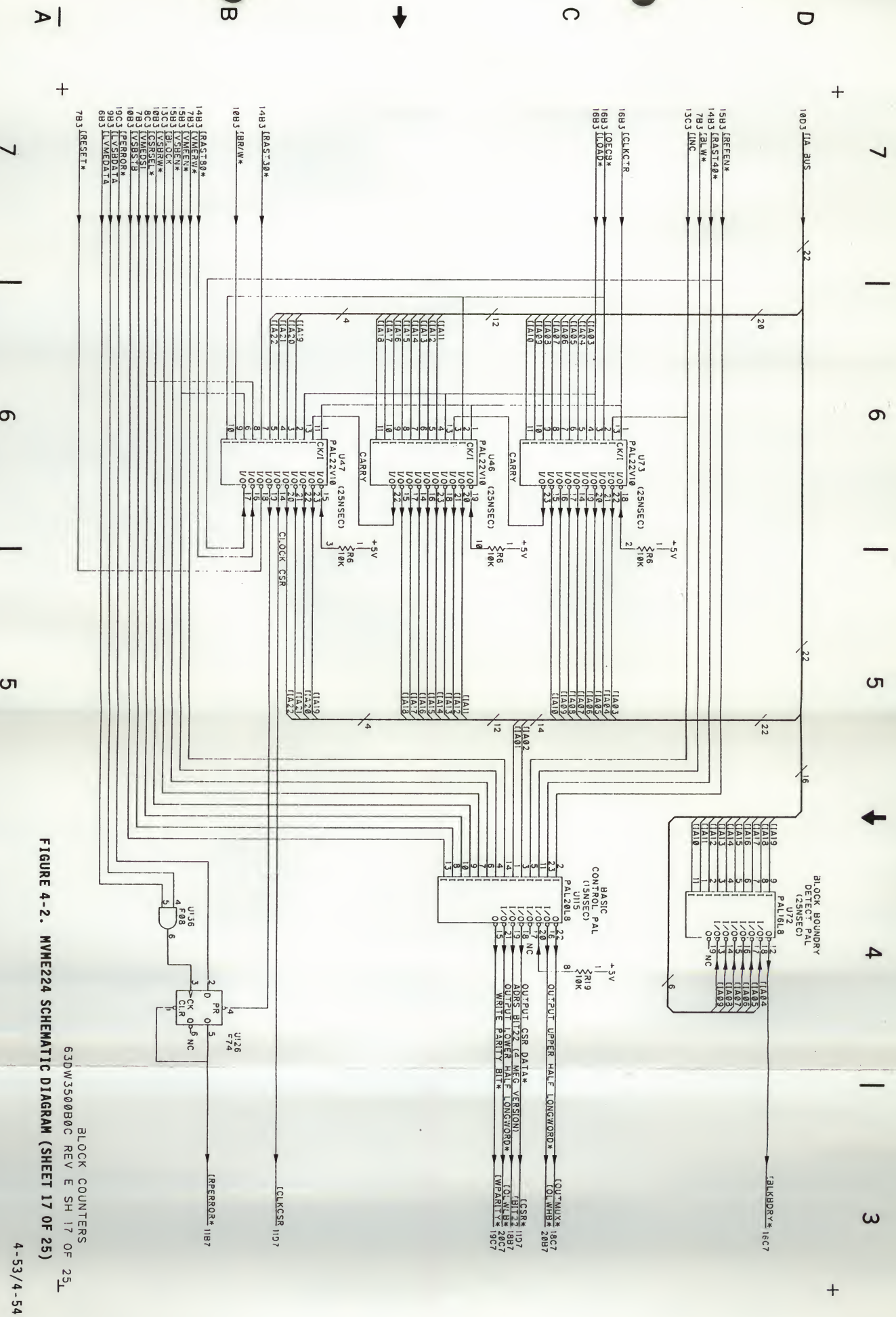
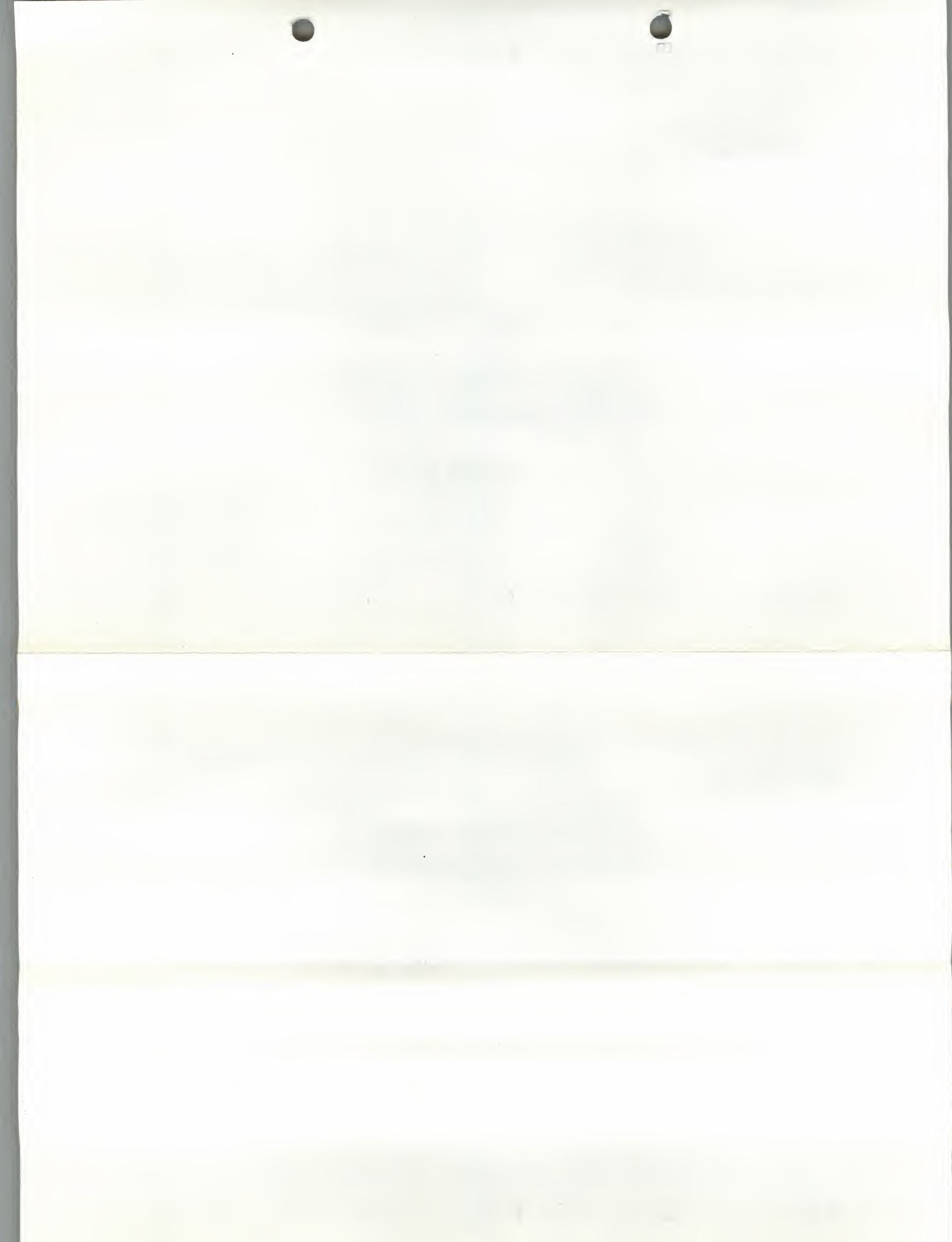


FIGURE 4-2. WVME224 SCHEMATIC DIAGRAM (SHEET 17 OF 25)



CONVERSION LIST

MVME224-2 8M byte Memory Module

Part Number	12 NC Number	Description
76430773	5322 209 73869	IC DELAY LINE 40NS
01NW9804C33	5322 209 72706	IC DELAY LINE 40NS
01NW9804C80	5322 209 73905	IC DELAY LINE 100NS
06SW-962A29		RES 150E 5% 0.125W
06SW-962A81		RES 22K . 5% 0.125W
21NW9604A58		CAP 330PFF 50V 5%
21NW9632A03	5322 122 33424	CAP 0.1UF 50VDC
21SW992C014		CAP 0.010F 50V CER
23NW9618A82	5322 124 41431	CAP 22UF 25V ELE
40NW9801A34	5322 277 11068	SWITCH DIP 8 POS.
48NW9612A59	5322 130 80846	LED GREEN
51-W4804C89		IC PAL
51-W4804C91		IC PAL
51-W4939B18		IC PAL
51-W5120C18		IC PAL
51-W5120C19		IC PAL
51-W5120C27		IC FROM
51-W5120C30		IC PAL
51-W5388B12		IC PAL
51-W5388B13		IC PAL
51-W5388B14		IC PAL
51-W5388B15		IC PAL
51-W5388B16		IC PAL
51-W5388B17		IC PAL
51-W5388B18		IC PAL
51-W5388B20		IC PAL
51-W5388B21		IC PAL
51-W5388B22		IC PAL
51-W5388B23		IC PAL
51-W5388B34		IC PAL
51-W5388B36		IC PAL
51-W5388B37		IC PAL
51-W5388B38		IC PAL
51-W5388B39		IC PAL
51-W5388B40		IC PAL
51-W5388B42		IC PAL
51-W5388B54		IC PAL
51-W5388B55		IC PAL
51-W5388B60		IC PAL
51-W5449B52		IC PAL
51-W5449B64		IC PAL

Part Number	12 NC Number	Description
51-W5473B08		IC PAL
51AW4591D23		IOC PAL
51AW4591D24		IOC PAL
51AW5100B09		IC PAL
51AW5120B72		IC PAL
51AW5120B73		IC PAL
51AW5120B75		IC PAL
51AW5120B76		IC PAL
51NW9615B65	5322 209 72472	IC MC1455P1
51NW9615C24	5322 209 81634	IC SN74LSJ2N
51NW9615F85	5322 209 85677	IC SN74S38N
51NW9615J39	5322 209 81474	IC 74F74PC
51NW9615K18	5322 209 81533	IC 74F373PC
51NW9615K47	5322 209 81128	IC 74F244PC
51NW9615K60		IC 74F158APC
51NW9615K65	5322 209 81538	IC 74F64PC
51NW9615K66	5322 209 71609	IC 74F32PC
51NW9615K67	5322 209 82013	IC 74F20PC
51NW9615K70	5322 209 72035	IC SN74AS08N/74F08PC
51NW9615K71	5322 209 81577	IC 74F04PC
51NW9615K73	5322 209 81534	IC 74F00PC
51NW9615K99	5322 209 81909	IC 74F374PC
51NW9615M90	5322 209 82169	IC 74F245PC
51NW9615R16	5322 209 71475	IC SN74ALS04AN
51NW9615R36	5322 209 73086	IC 74F543PC
51NW9615U44		IC M5M4C1000L-10
51NW9615V22		IC TC511001Z-10
51NW9615V91		IC SN74AS280N
51NW9615W26		IC DS1000M-100
51NW9615W31		IC SN74AS841NT
51NW9615W46		IC DS1000M-50
51NW9626A49	5322 116 90516	RNW 7X10K
51NW9626B01		RNW 4-330 8P
51NW9626B47		RNW 9-22K 10P
51NW9626B56	5322 116 90502	RNW 9X10K
64-W5501B01		FRONT PNL MVME224-2
84-W8500B01		MVME224-2 8MB PCB

